

# First Results from the HPAD 0.1 Chip

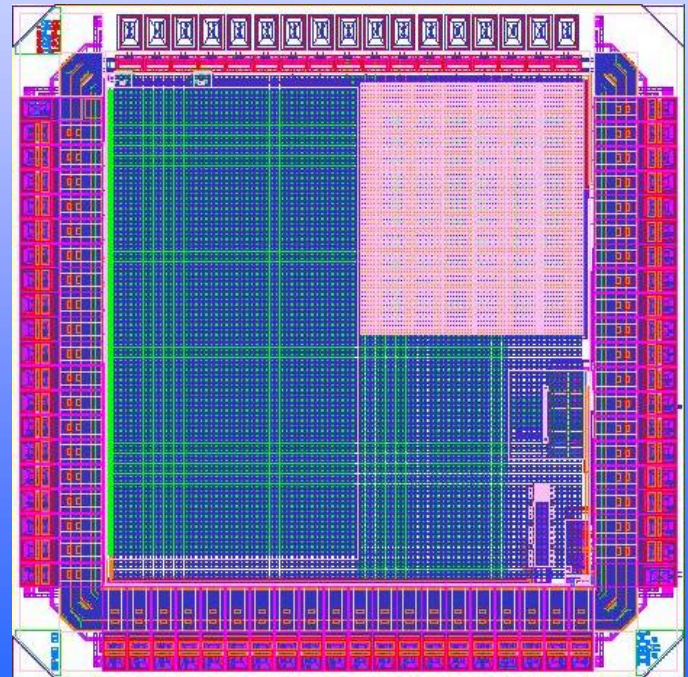
U. Trunk  
DESY

# The "hpad 0.1" chip

- 2mm x 2mm, submitted via MOSIS at 26.03.2008
- Only test structures:
  - Capacitors
  - Switches (FETs)
  - 16-cell analogue storage array
  - OP-Amp & buffer amplifiers
  - Minimum protection pad

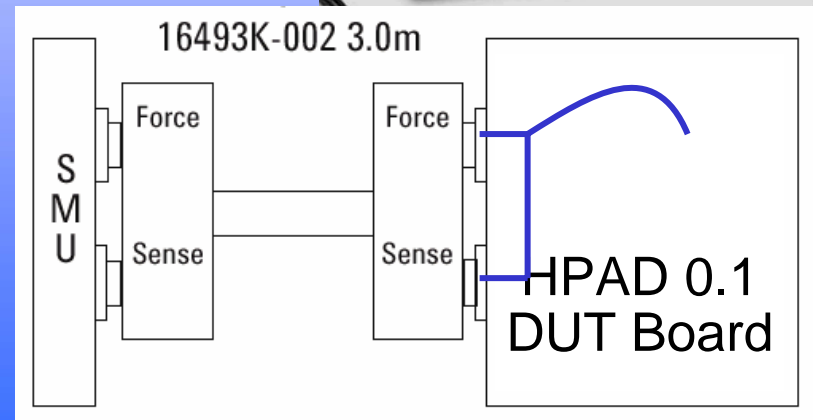
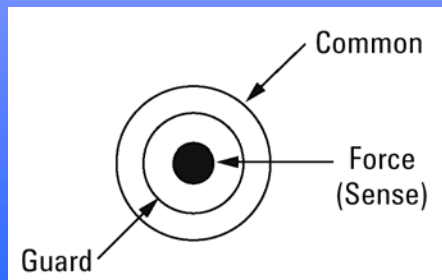
All results are...

- preliminary!
- per device (unless denoted else)



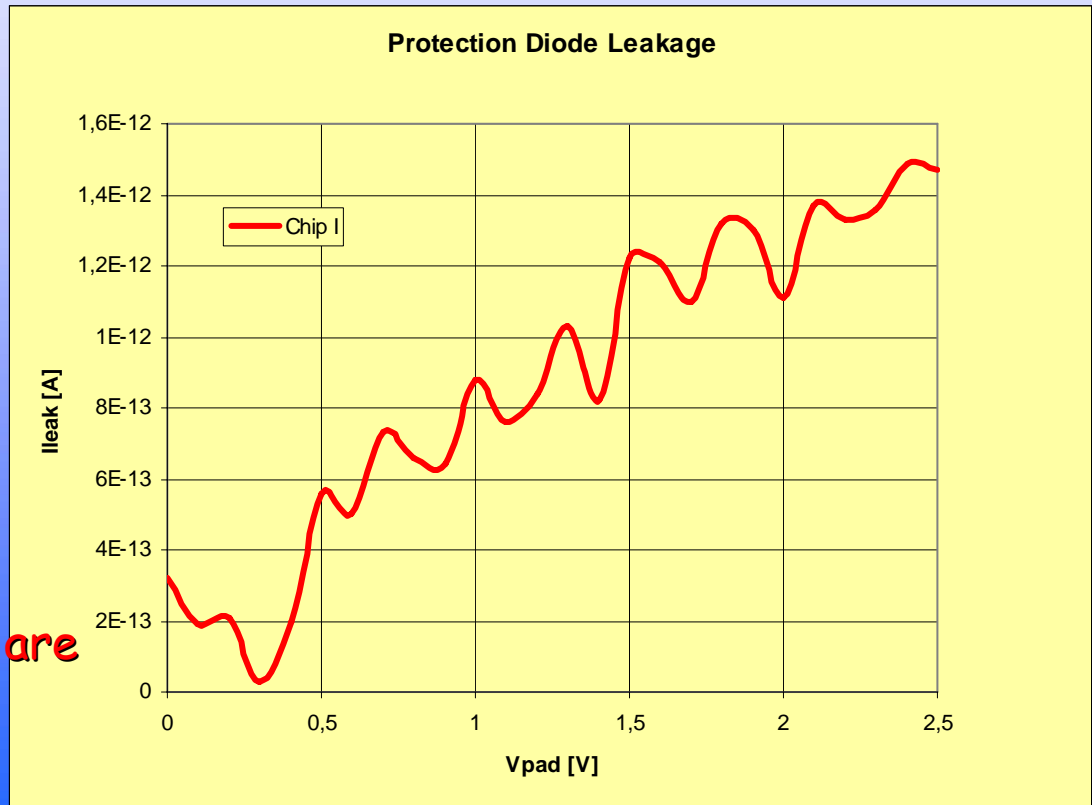
# Measurement Setup

- HP 4156A high-precision semiconductor parameter tester
  - 4 HRSMUs (1fA res, 20fA accuracy)
  - 4-wire Kelvin connections via Triax cables
- Custom made HPAD 0.1 DUT board
  - Flying leads & pin headers to connect to analyzer
  - CLCC 84 carrier & test socket
  - >5mm wire spacing when possible
  - Special cleaning procedure



# Protection Diode Leakage

- Input of 'Buffer25'
  - ARM pad w. protection structures
  - Single ZVTDGNMOS gate
  - Defines basic accuracy, for which the following results are not corrected



# Capacitors on "hpad 0.1"

- DGNCAP (thick-oxide NMOS) array

- 5.0 $\mu\text{m}$  · 5.0 $\mu\text{m}$
- 51.1...145.7fF
- 8880 cells

$$\Delta U = \frac{t_{\text{store}} \cdot I_{\text{leak}}}{C_{\text{store}}}$$

- MIM cap array

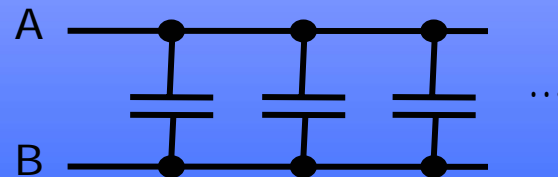
- 5.24 $\mu\text{m}$  · 5.24 $\mu\text{m}$
- 59.57fF
- 8400 cells

$$\left. \begin{array}{l} C_{\text{store}} = 100\text{fF} \\ t_{\text{store}} = 100\text{ms} \end{array} \right\} I_{\text{leak}} \leq 1\text{fA}$$

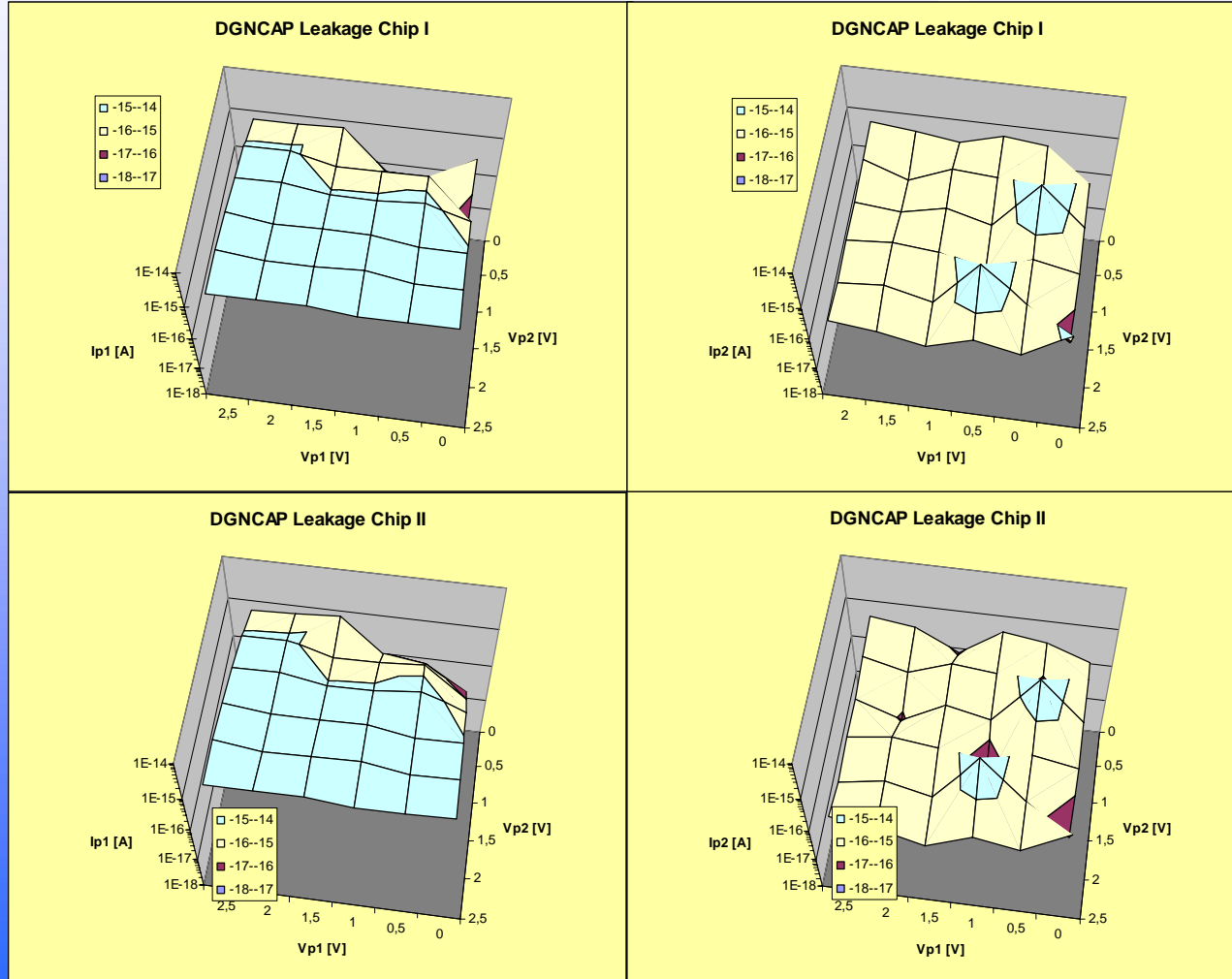
$$\Delta U \leq 1\text{mV (1\% @ 1V)}$$

- Dual MIM cap array

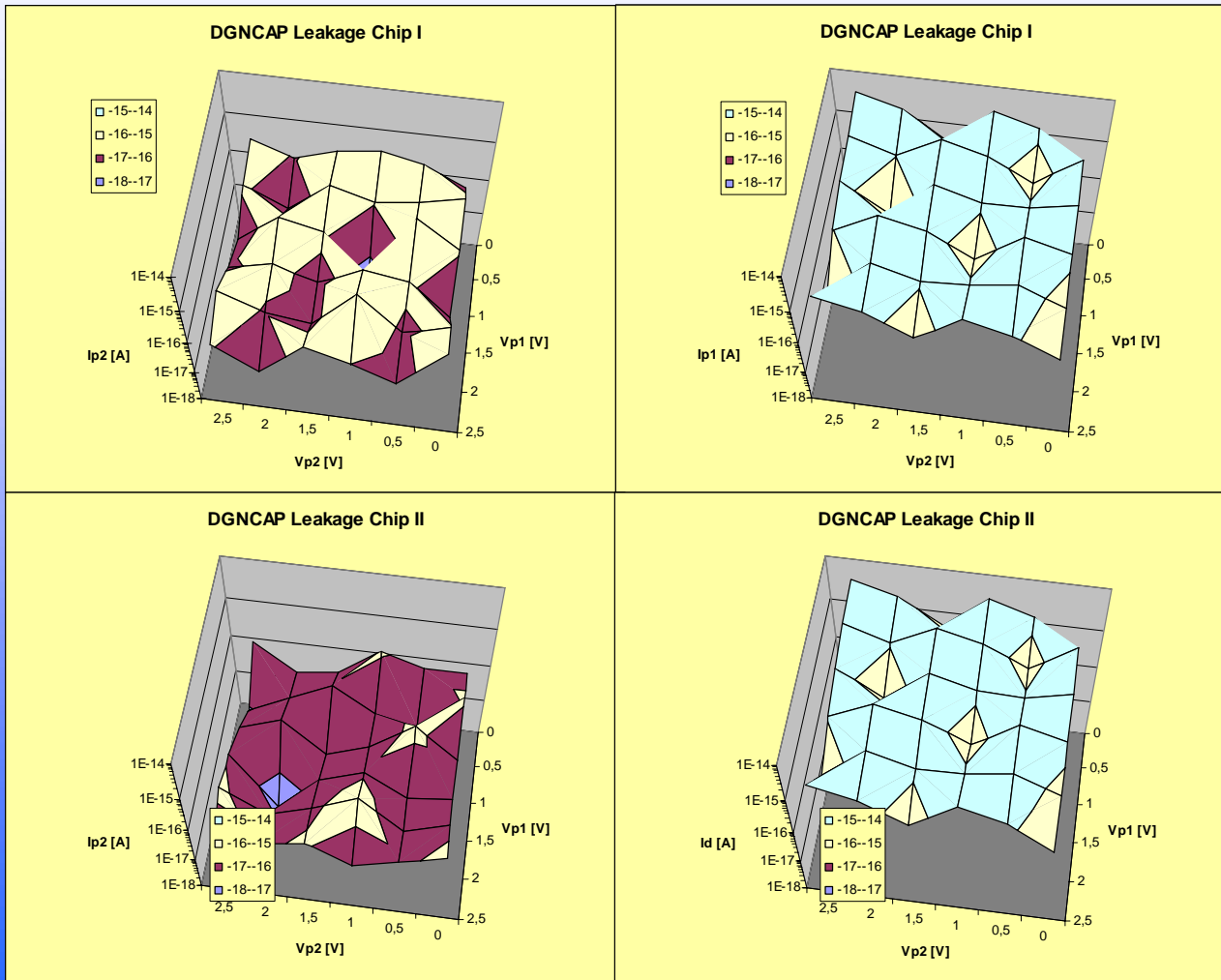
- 8.5 $\mu\text{m}$  · 8.5 $\mu\text{m}$
- 680.17fF
- 876 cells



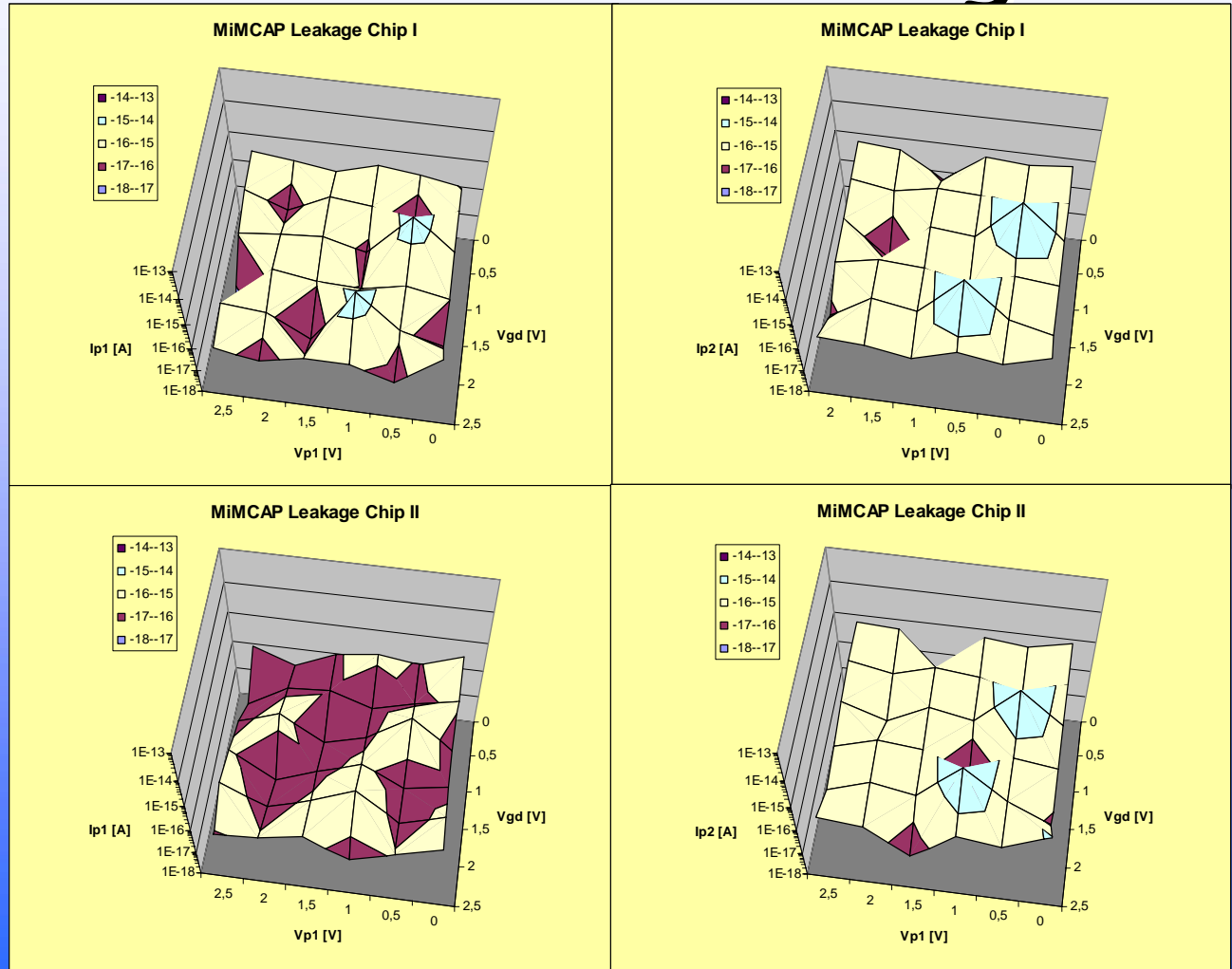
# DGNCAP Leakage



# DGNCAP Leakage

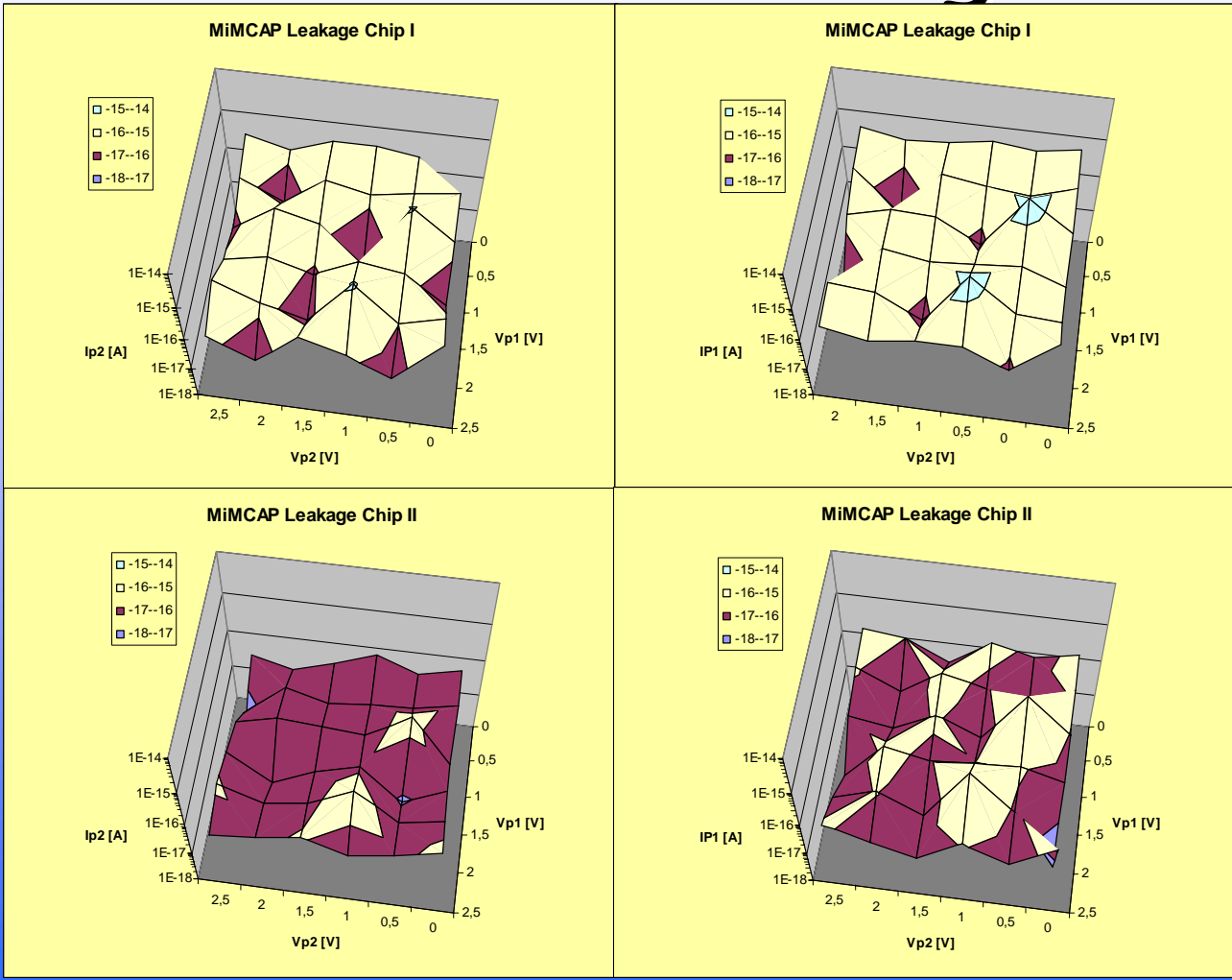


# MiMCP Leakage

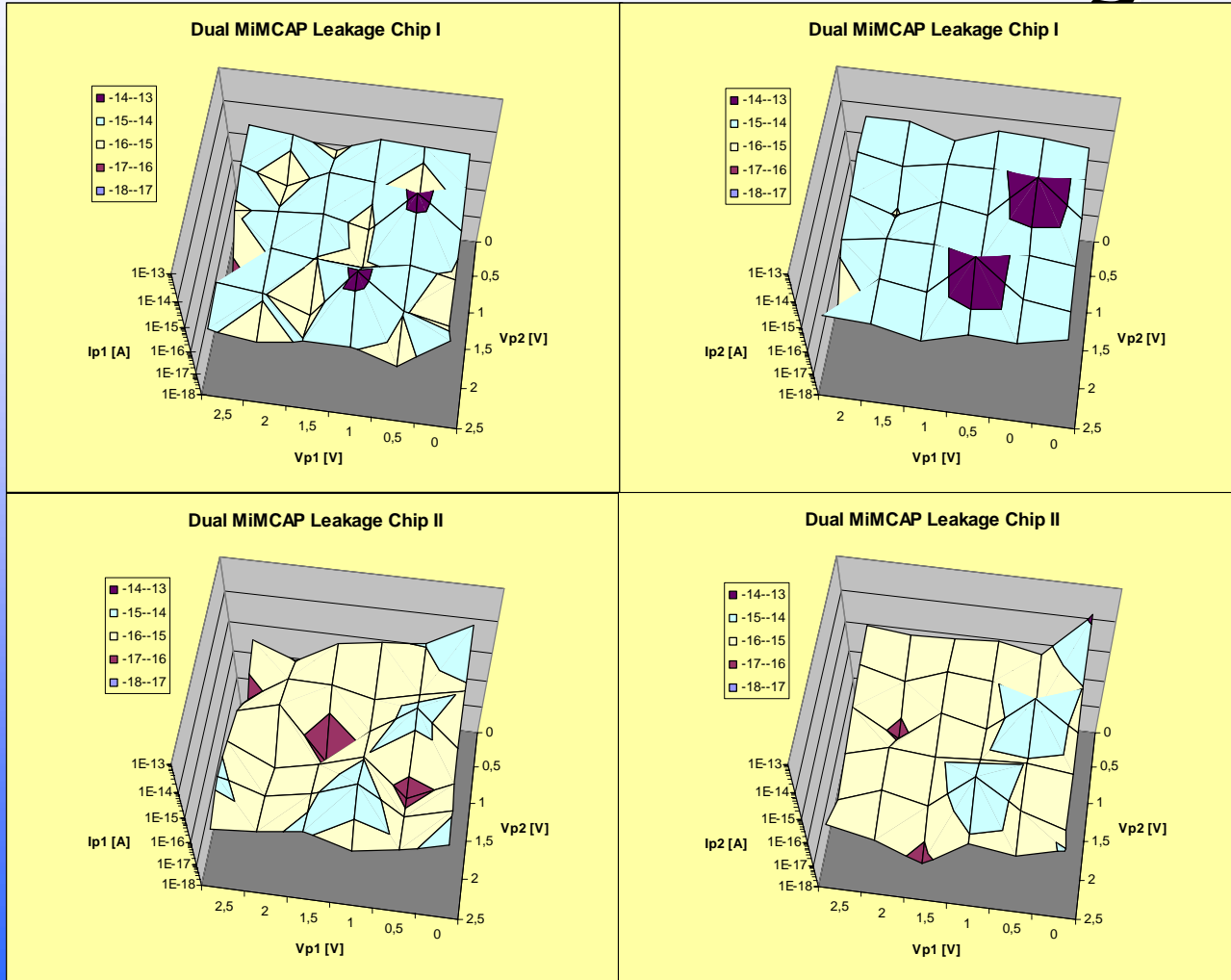




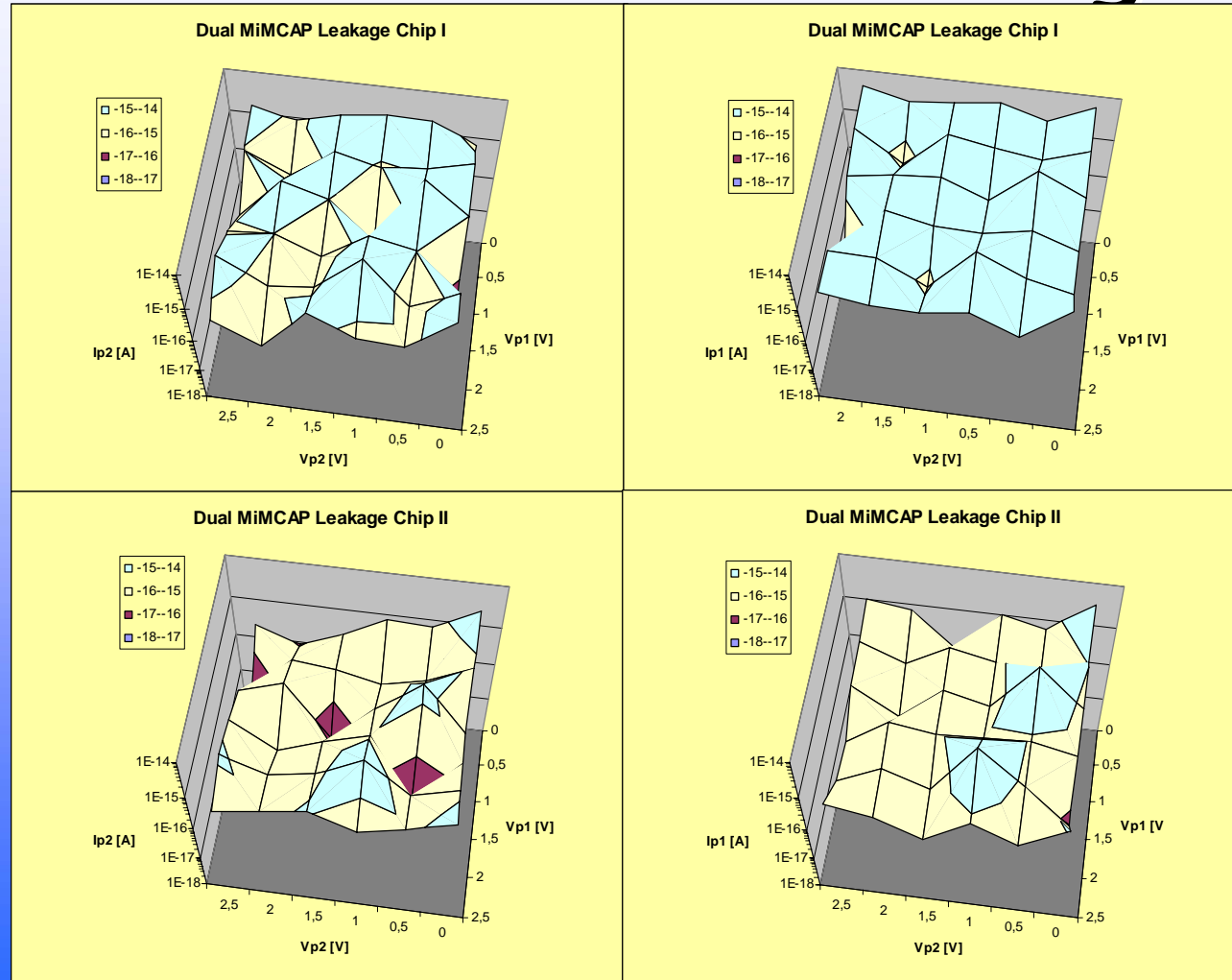
# MiMCAP Leakage



# Dual MiMCAP Leakage

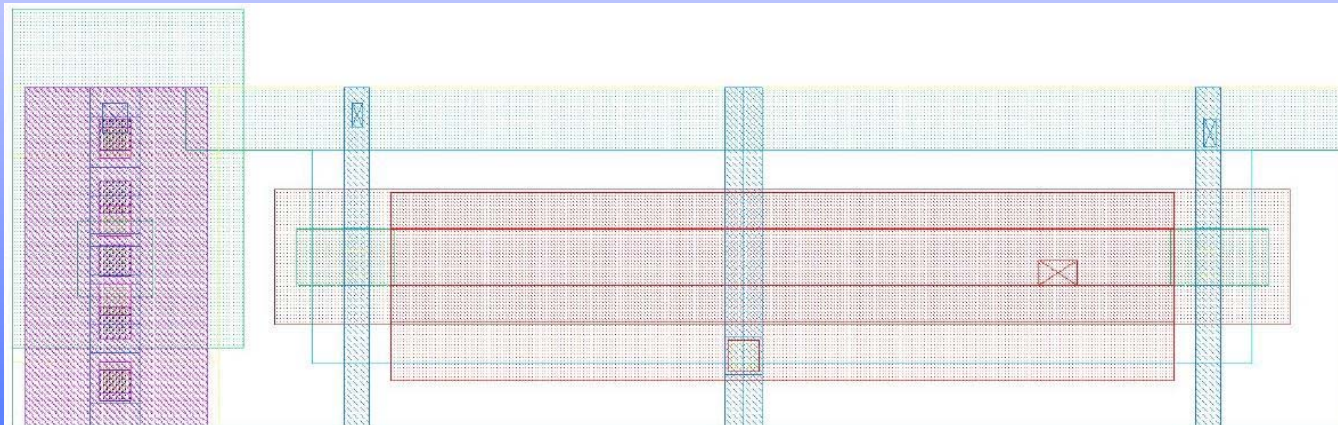


# Dual MiMCAP Leakage

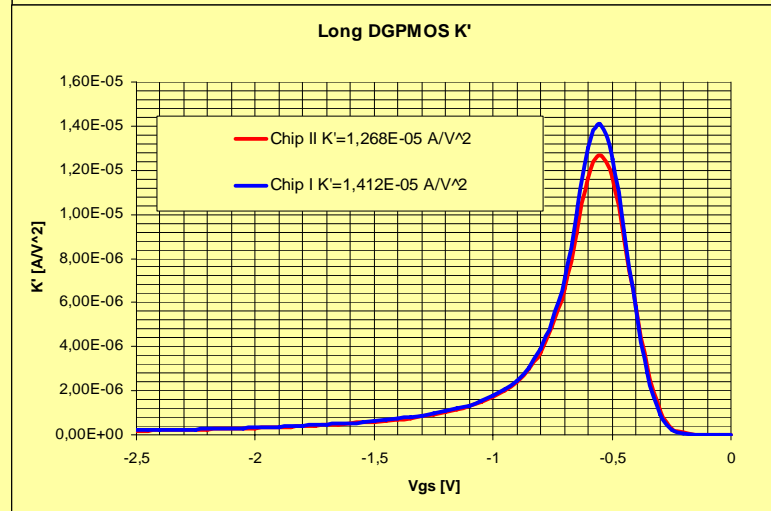
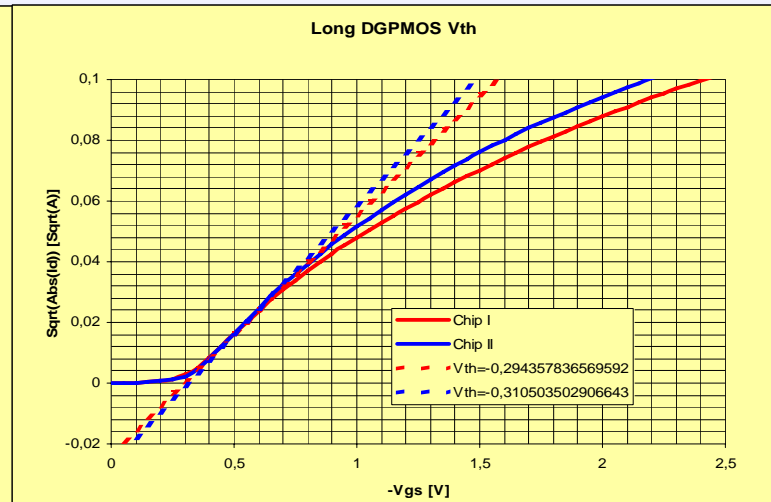
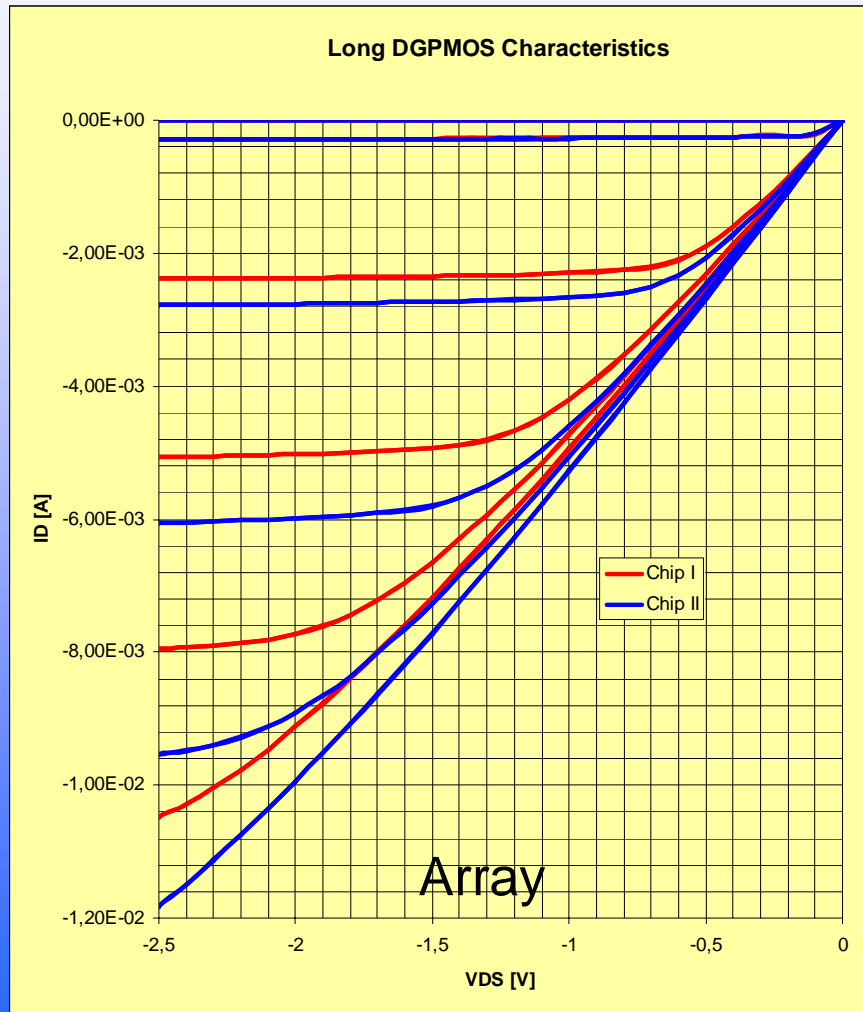


# Linear FET switches on "hpad 0.1"

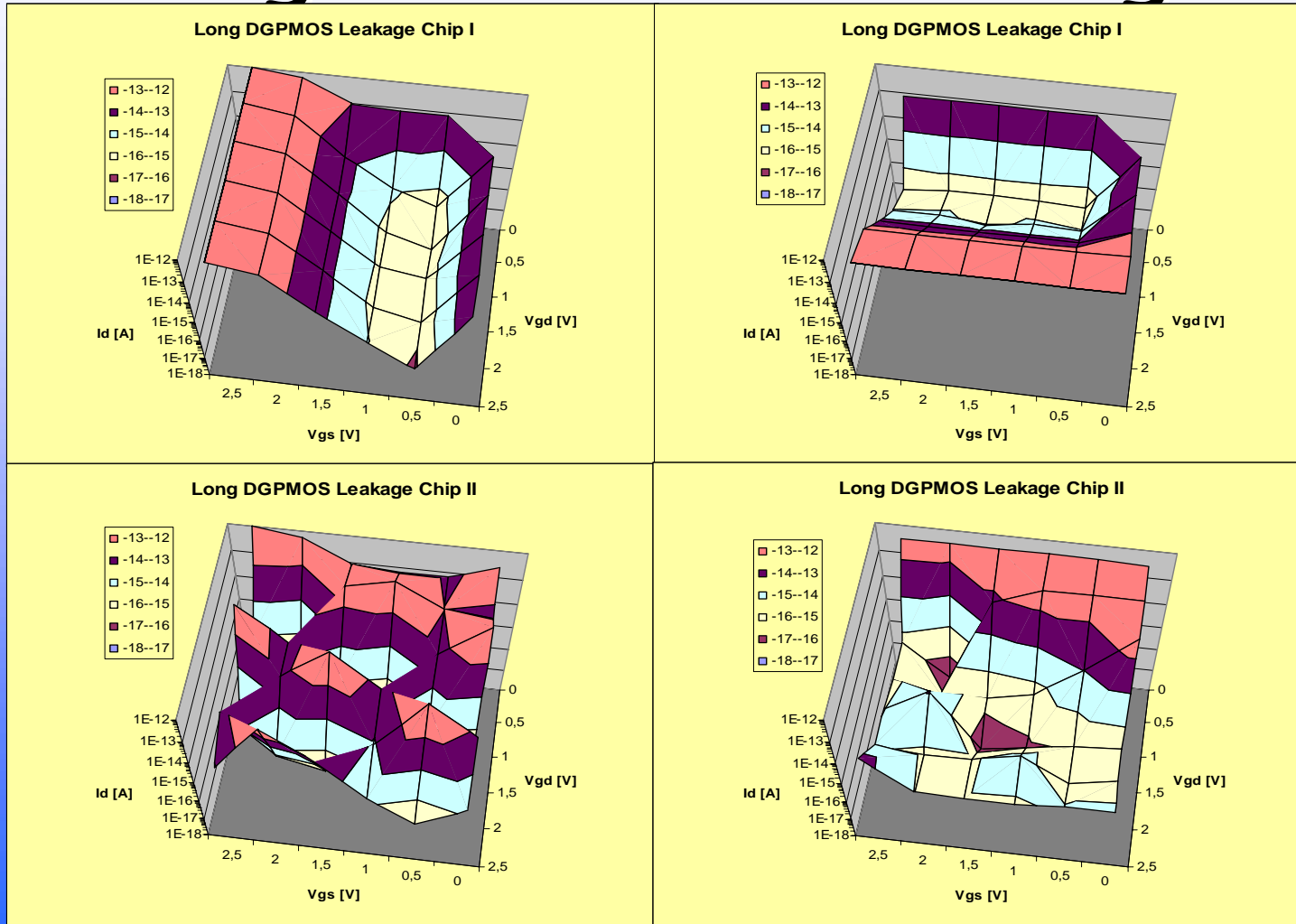
- Long DGPMOS (thick-oxide PMOS) switch array
  - $W/L = 0.36\mu\text{m} / 5.0\mu\text{m}$
  - 27142 cells



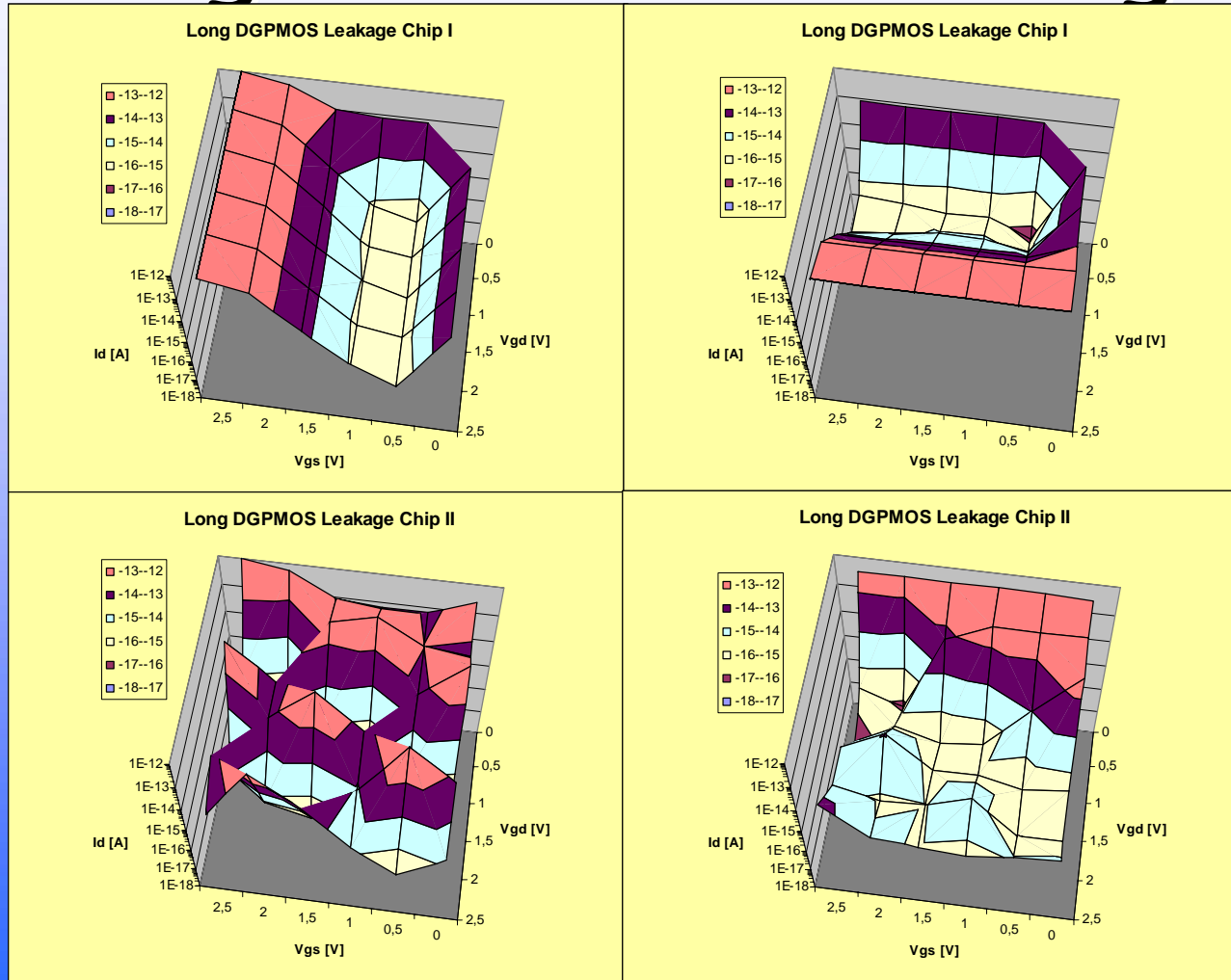
# Long DGPMOS Characteristics



# Long DGPMOS Leakage

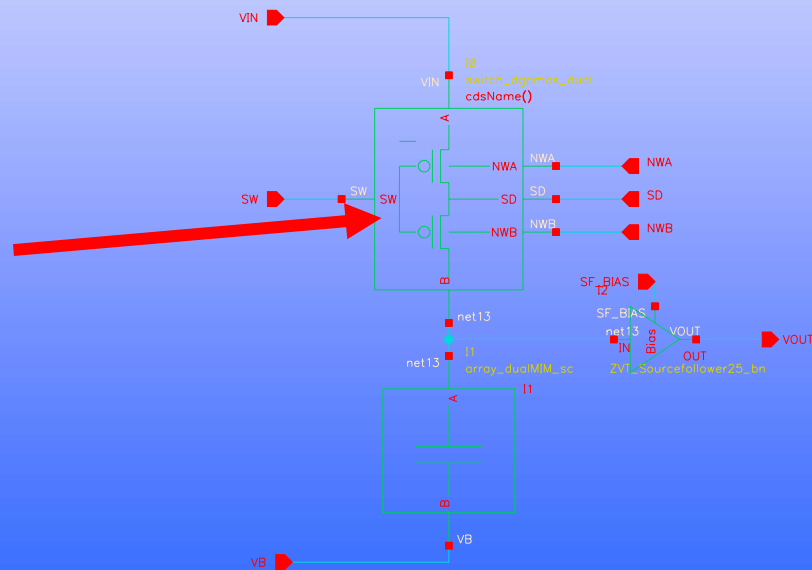


# Long DGPMOS Leakage



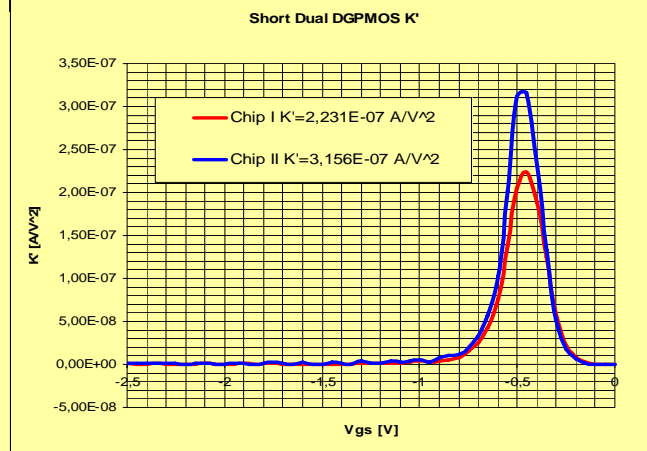
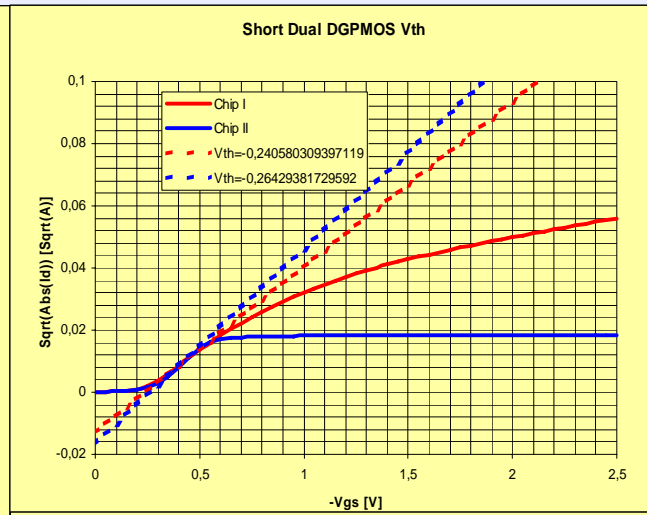
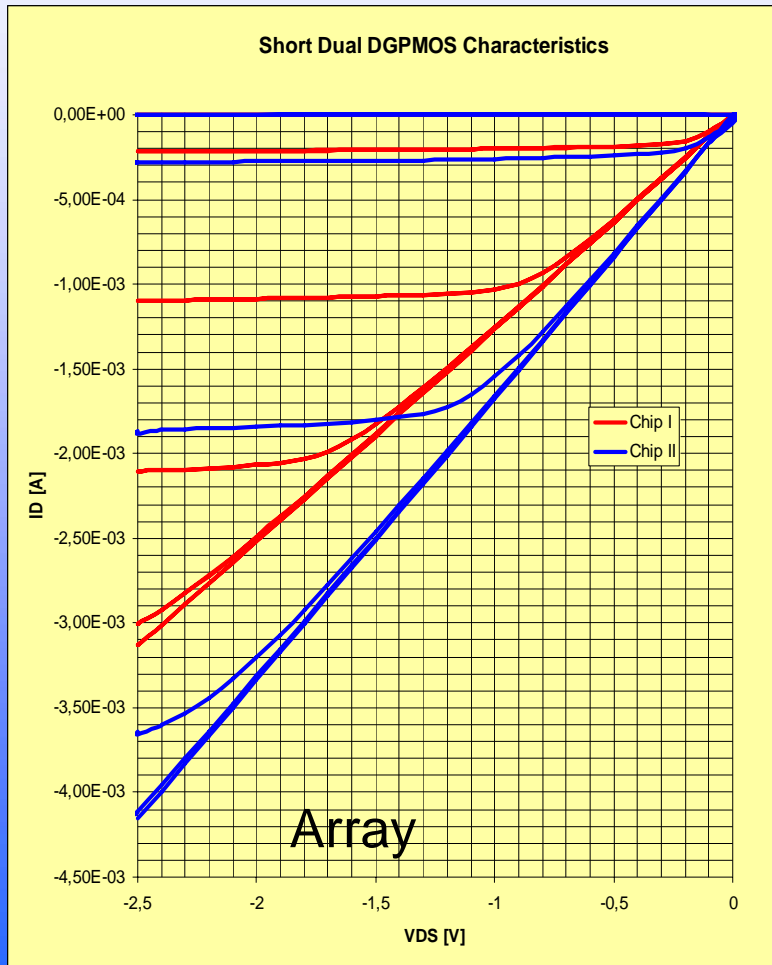
# Dual PMOS switches on "hpad 0.1"

- Array of dual DGPMOS switches
  - W/L  $0.36\mu\text{m}/2\mu\text{m}$  and  $0.36\mu\text{m}/0.24\mu\text{m}$

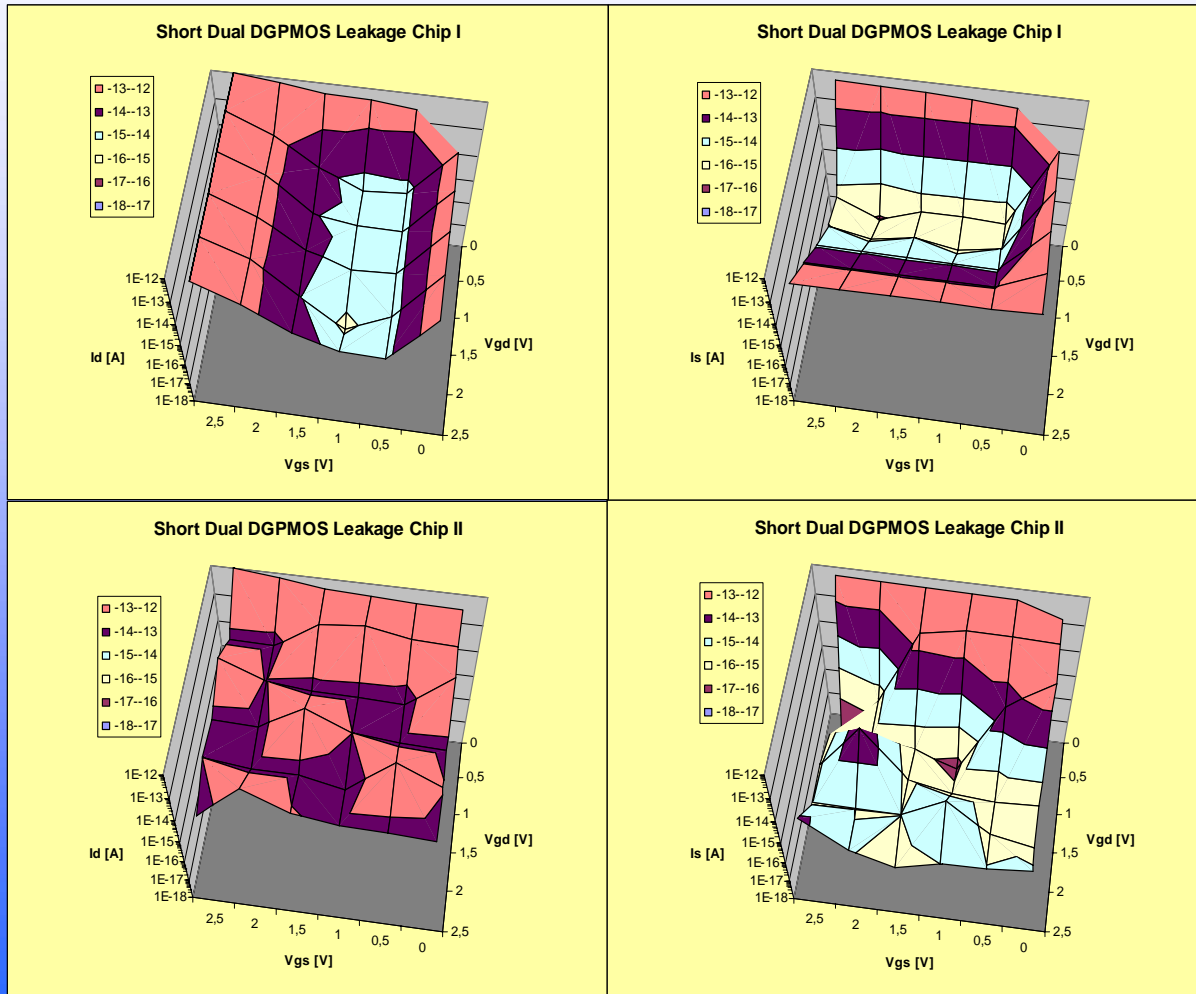




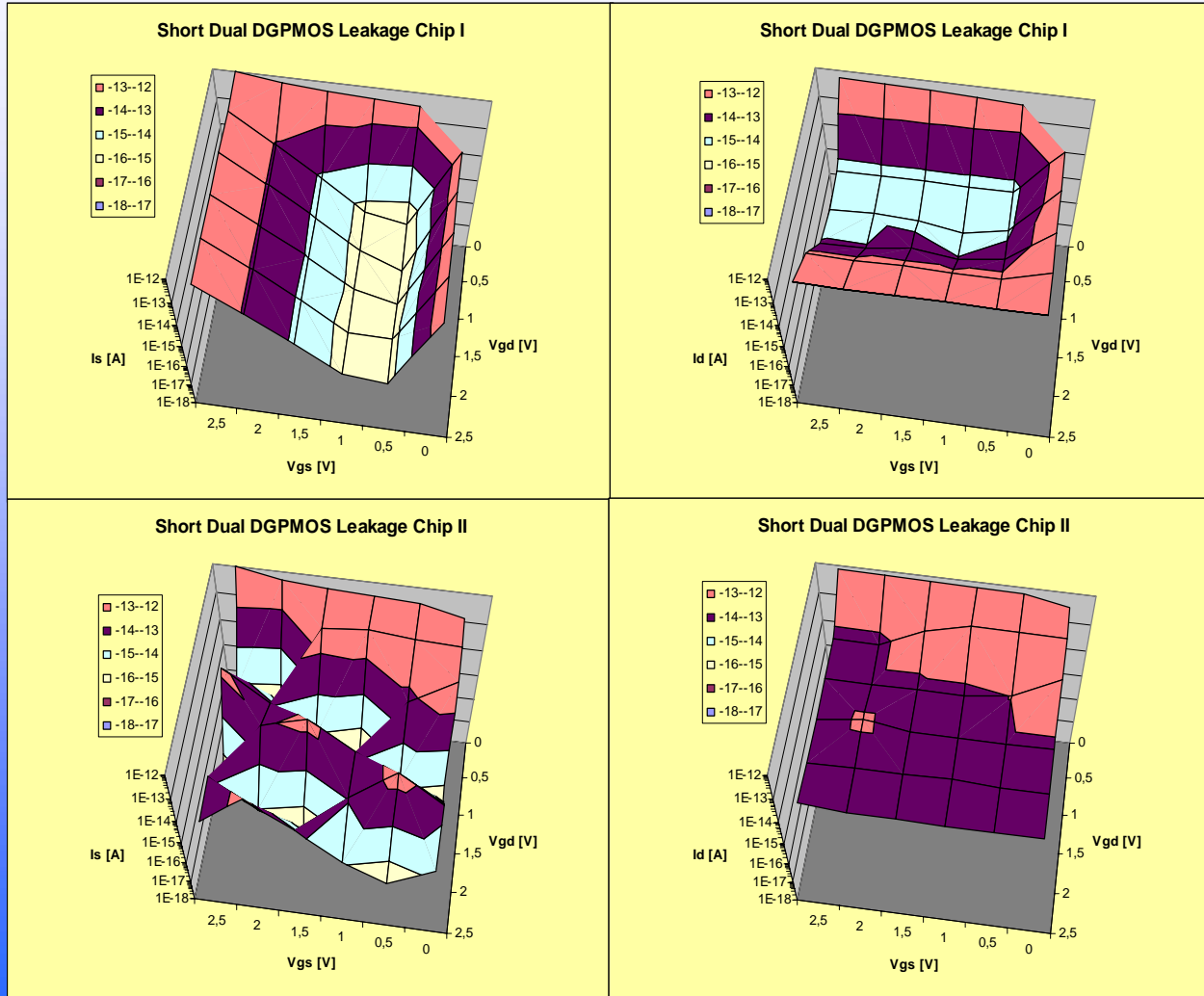
# Short Dual PMOS Characteristics



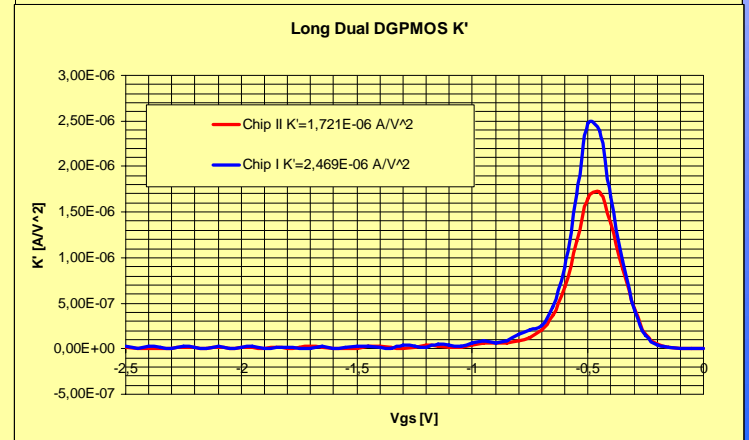
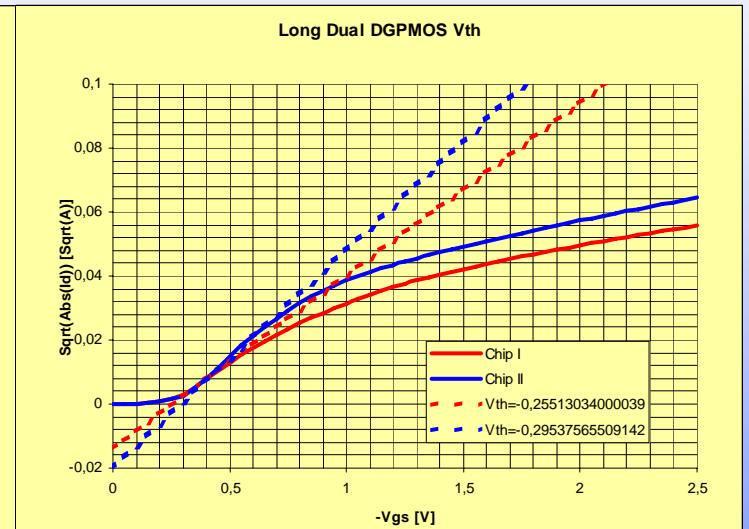
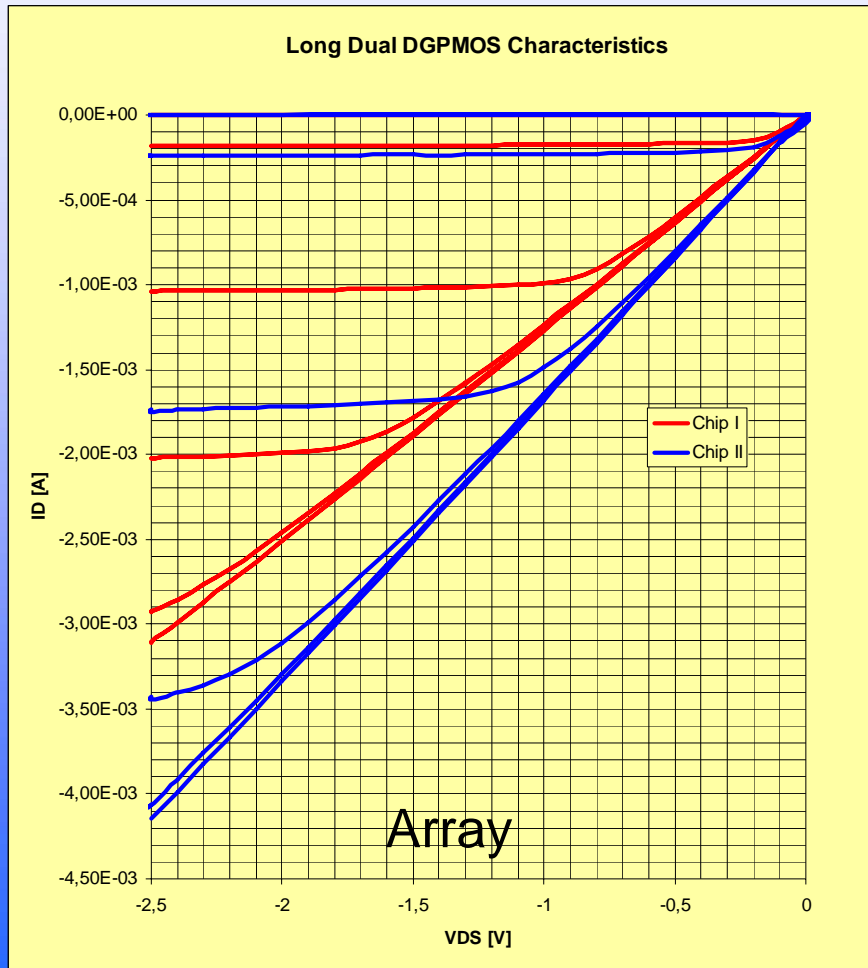
# Short Dual PMOS Leakage



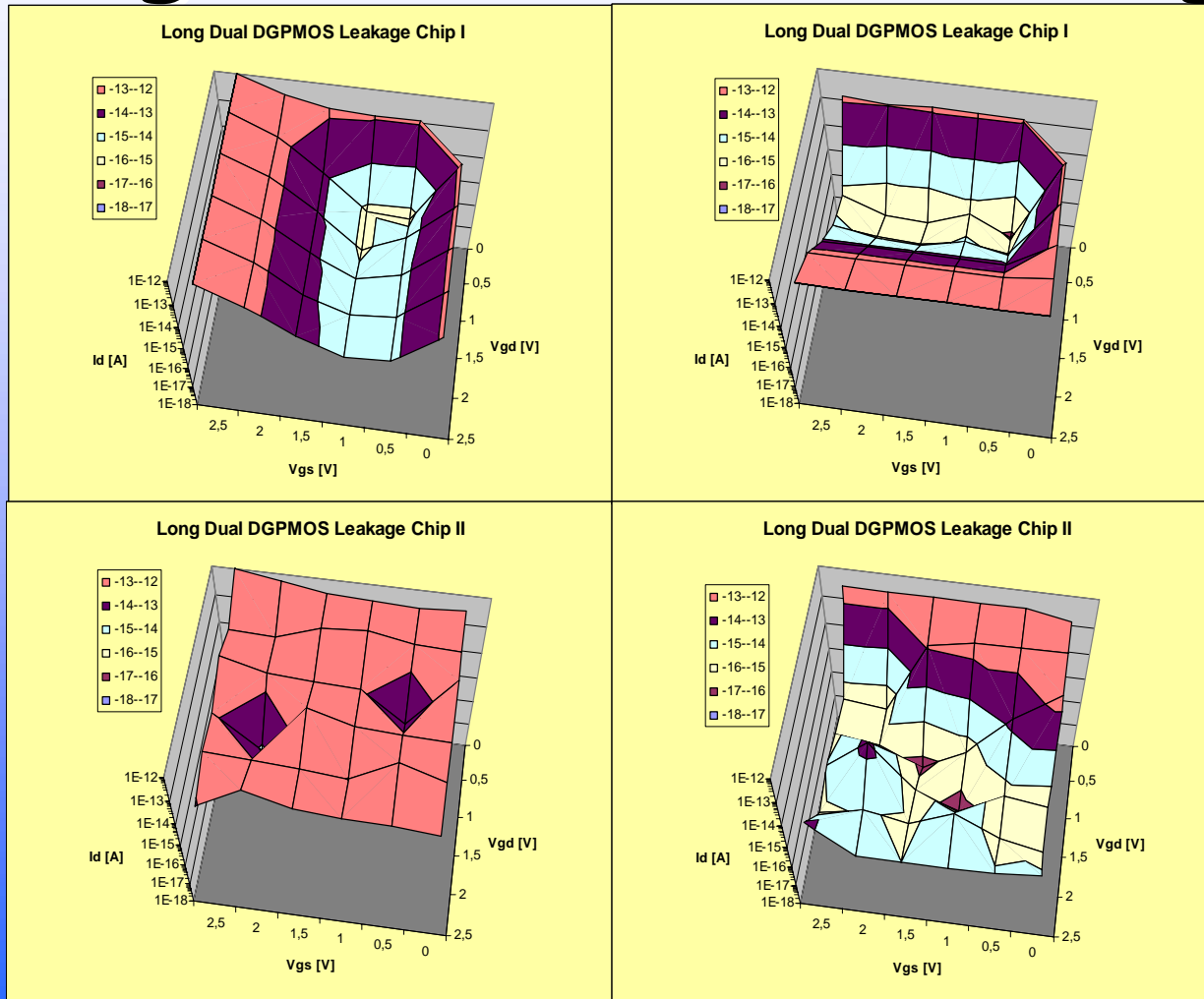
# Short Dual PMOS Leakage



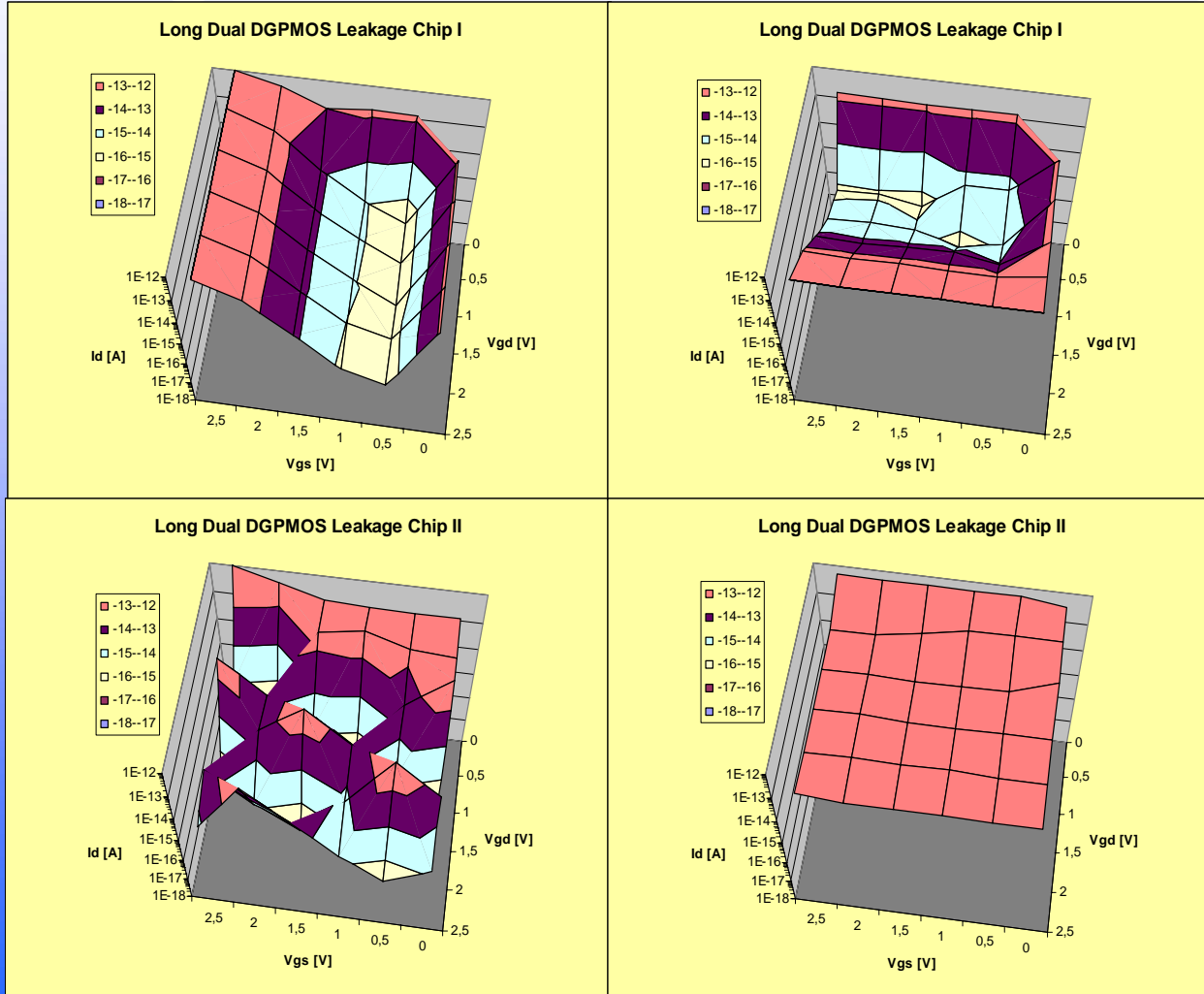
# Long Dual PMOS Characteristics



# Long Dual PMOS Leakage

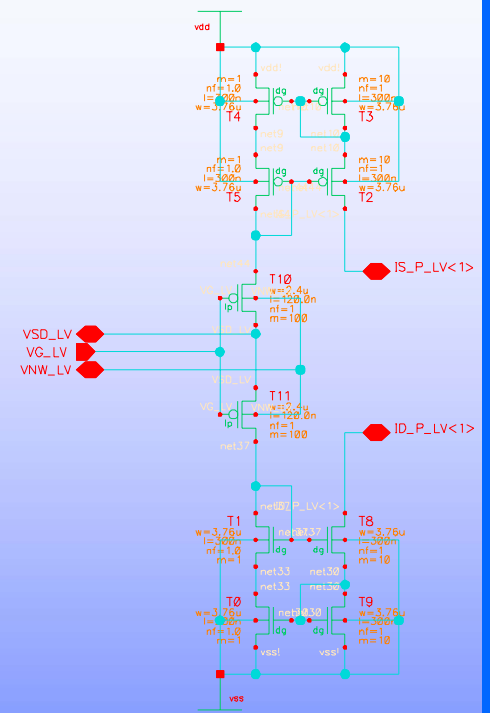


# Long Dual PMOS Leakage



# Enclosed FET switches on "hpad 0.1"

- LPPMOS (thin-oxide high-Vt PMOS)
- LPNMOS (thin-oxide high-Vt NMOS)
- DGPMOS (thick-oxide PMOS)
- DGNMOS (thick-oxide NMOS)
- 100 or 200 transistors
- Different W/L
- S & D readout via x10 cascaded current mirrors
- Results not corrected for multiples & CM ratio!

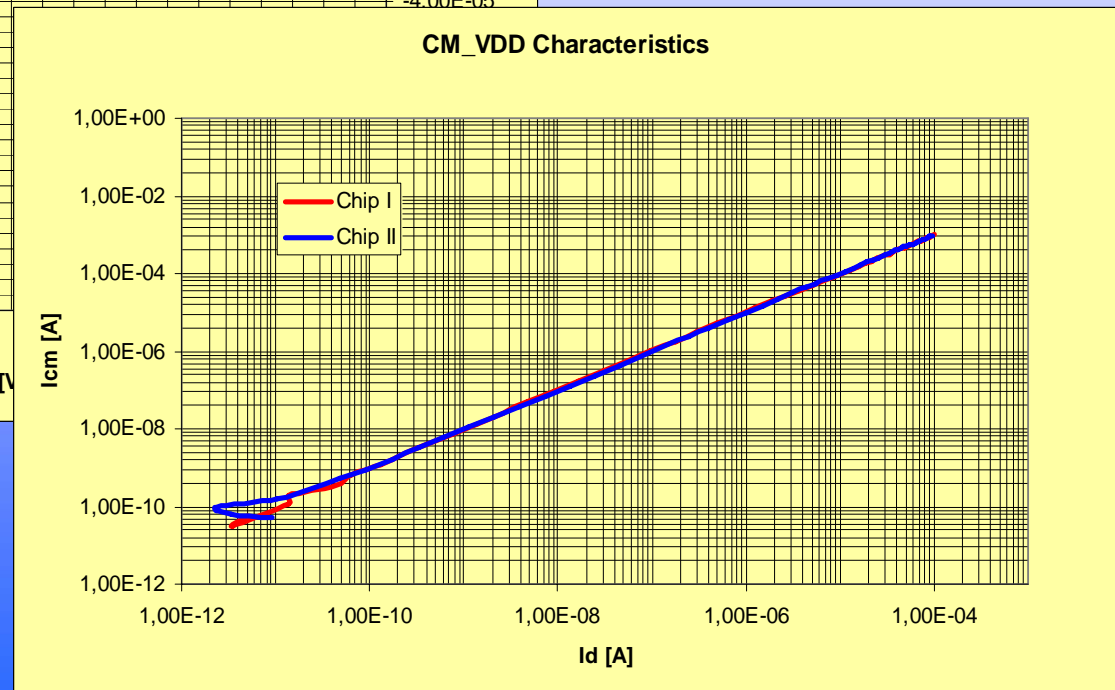
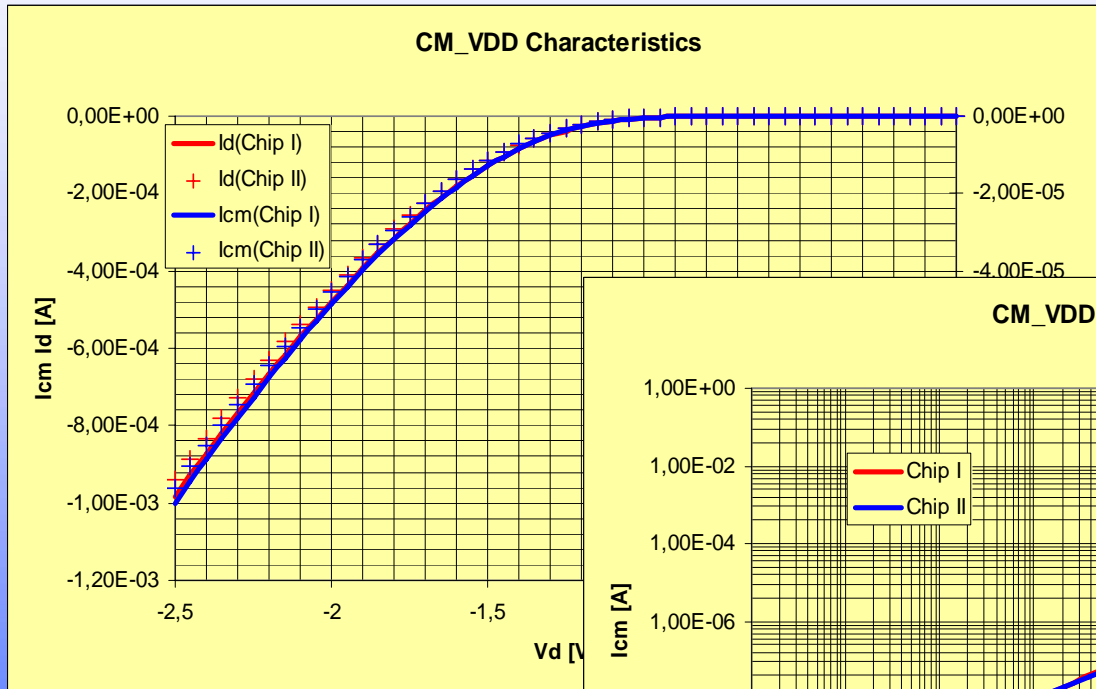


# Enclosed FET switches on "hpad 0.1"

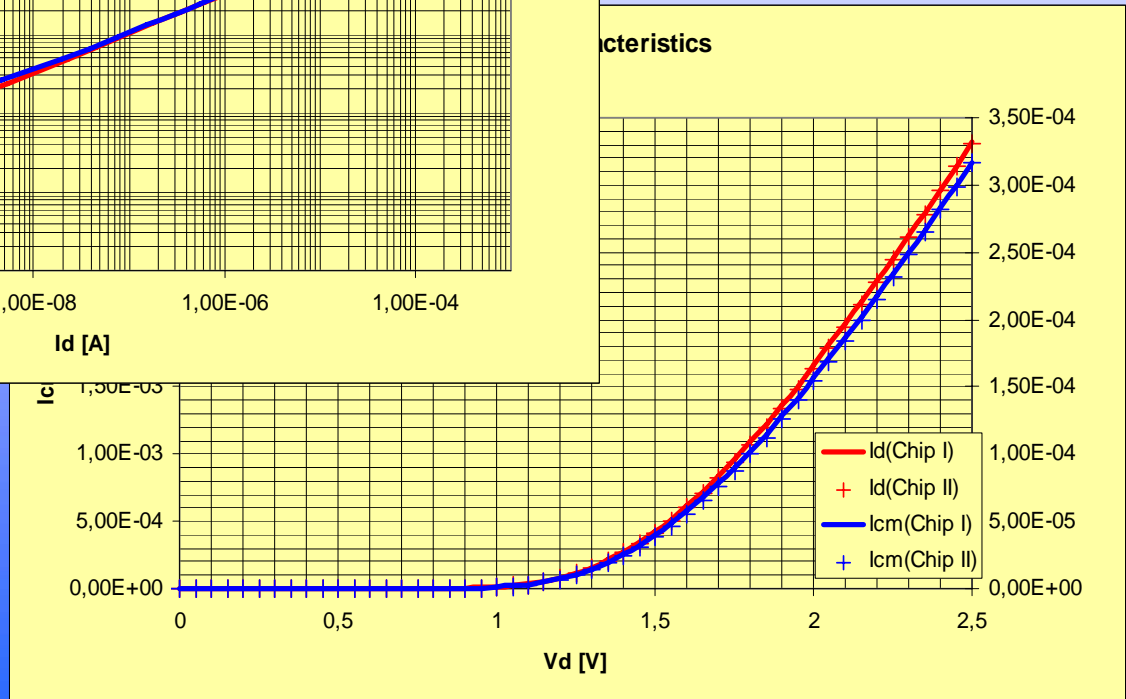
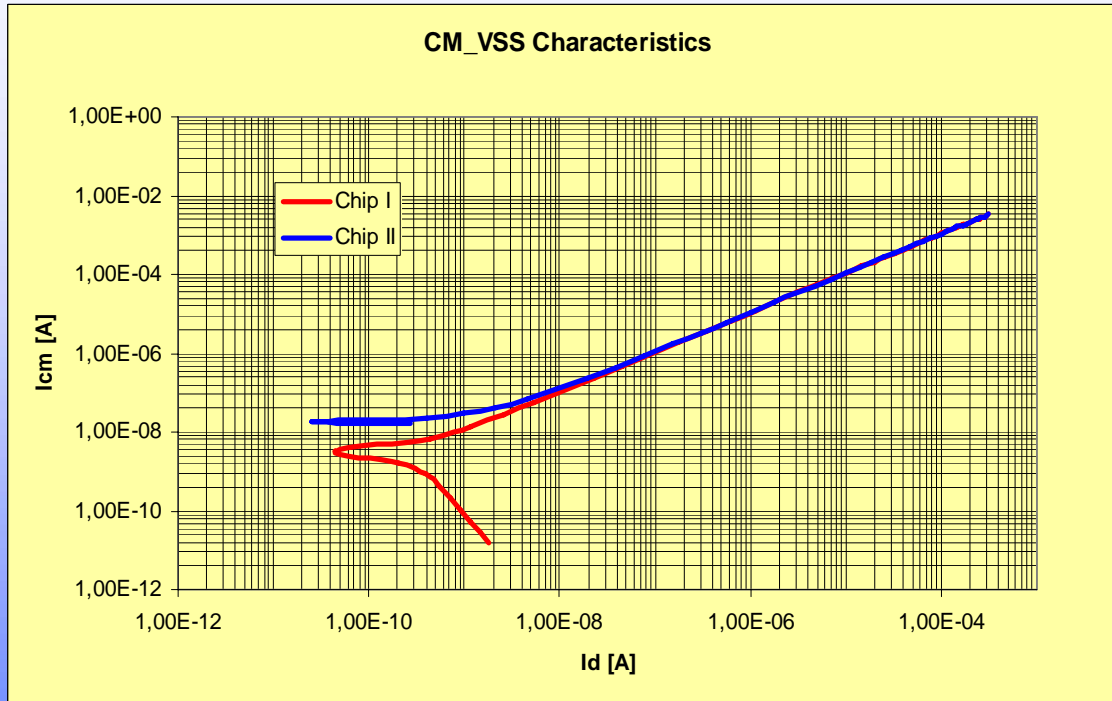
Nr.	Transistor Type [1]	W [μm]	L [μm]	Multi-plier	Source Node	Drain Node
1	LPNMOS	3.040	12100	IS N	LV< 1 >	ID N LV< 1 >
2	LPNMOS	3.040	24100	IS N	LV< 2 >	ID N LV< 2 >
3	LPNMOS	3.040	24200	IS N	LV< 3 >	ID N LV< 3 >
4	LPPMOS	3.040	12100	IS P	LV< 1 >	ID P LV< 1 >
5	LPPMOS	3.040	24100	IS P	LV< 2 >	ID P LV< 2 >
6	LPPMOS	3.040	24200	IS P	LV< 3 >	ID P LV< 3 >
7	DGNMOS	3.040	24100	IS N	DG< 1 >	ID N DG< 1 >
8	DGNMOS	3.040	24200	IS N	DG< 2 >	ID N DG< 2 >
9	DGPMOS	3.040	24100	IS P	DG< 1 >	ID P DG< 1 >
10	DGPMOS	3.040	24200	IS P	DG< 2 >	ID P DG< 2 >



# VDD Current Mirror

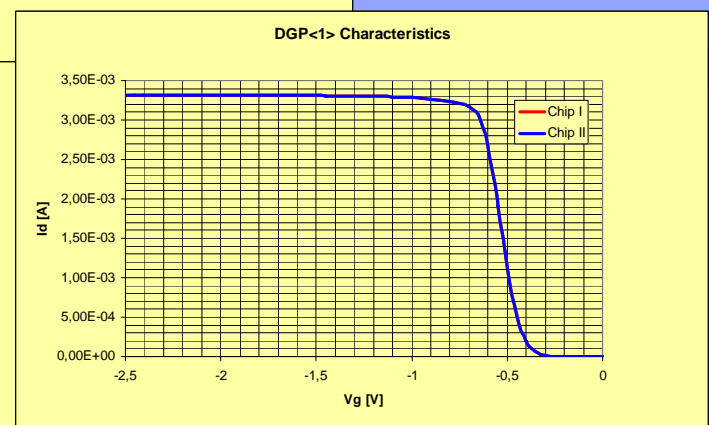
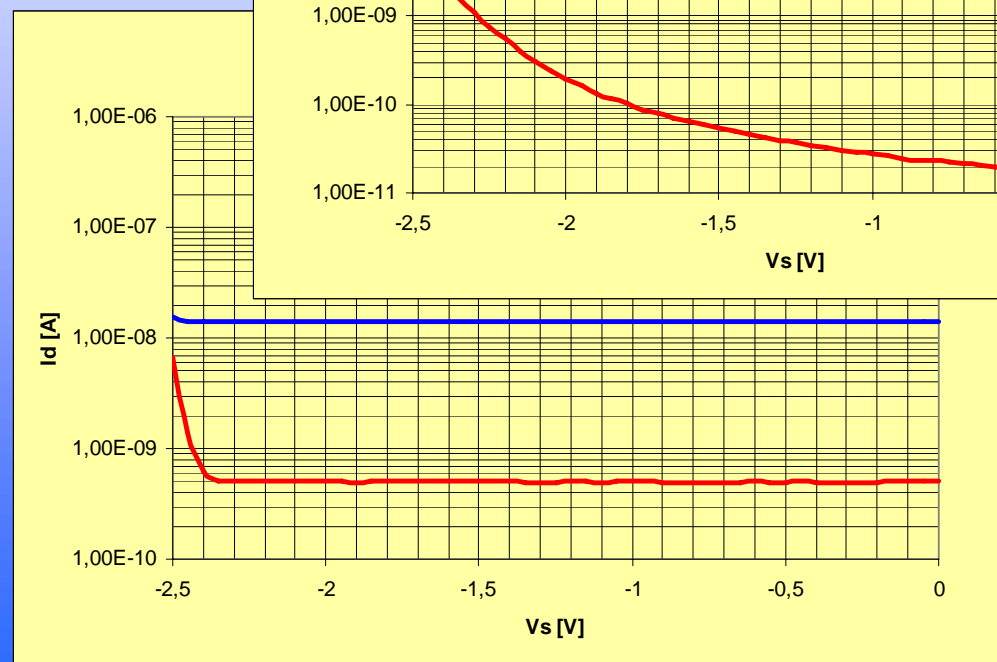
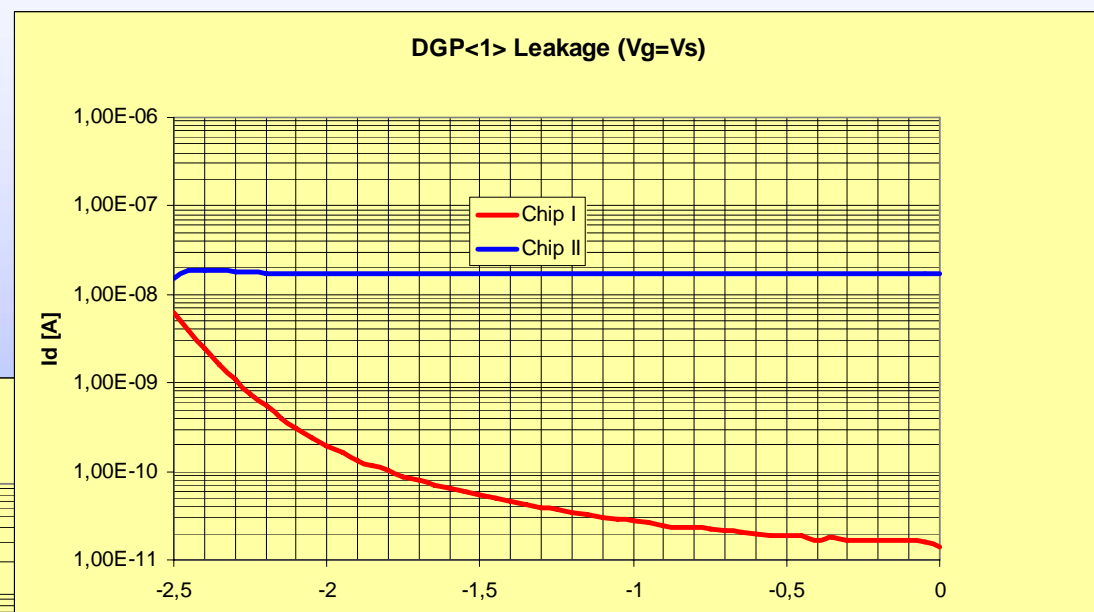


# VSS Current Mirror



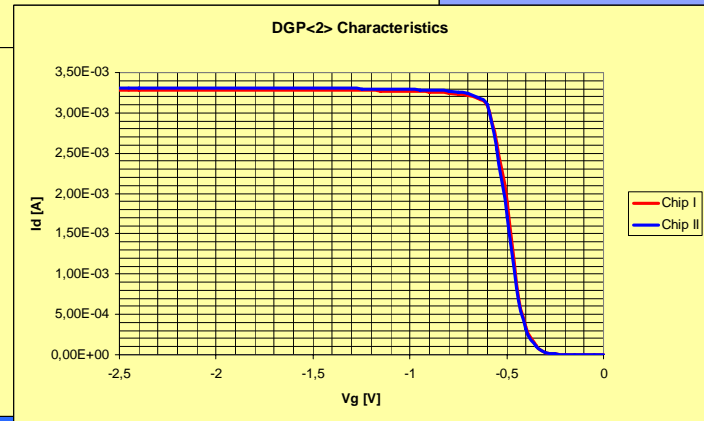
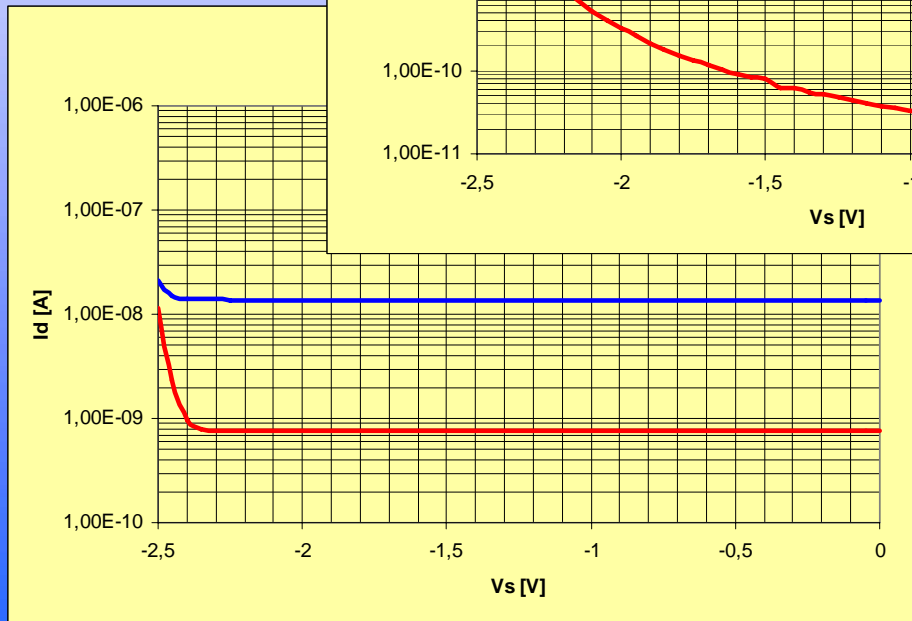
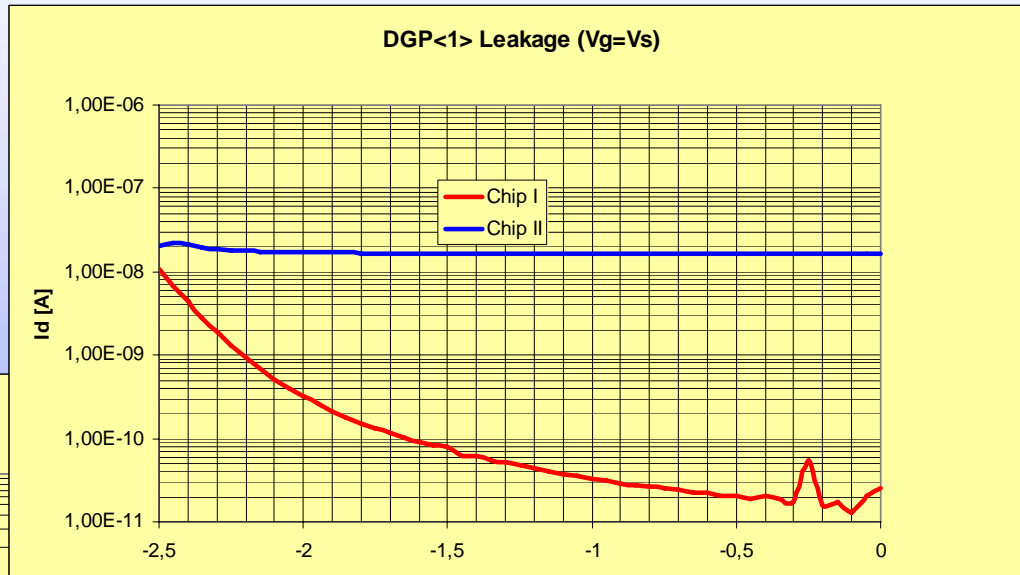
# DGPMOS<1>

$W=3.04\mu\text{m}$   
 $L=0.24\mu\text{m}$   
 $N=100$



# DGPMOS<2>

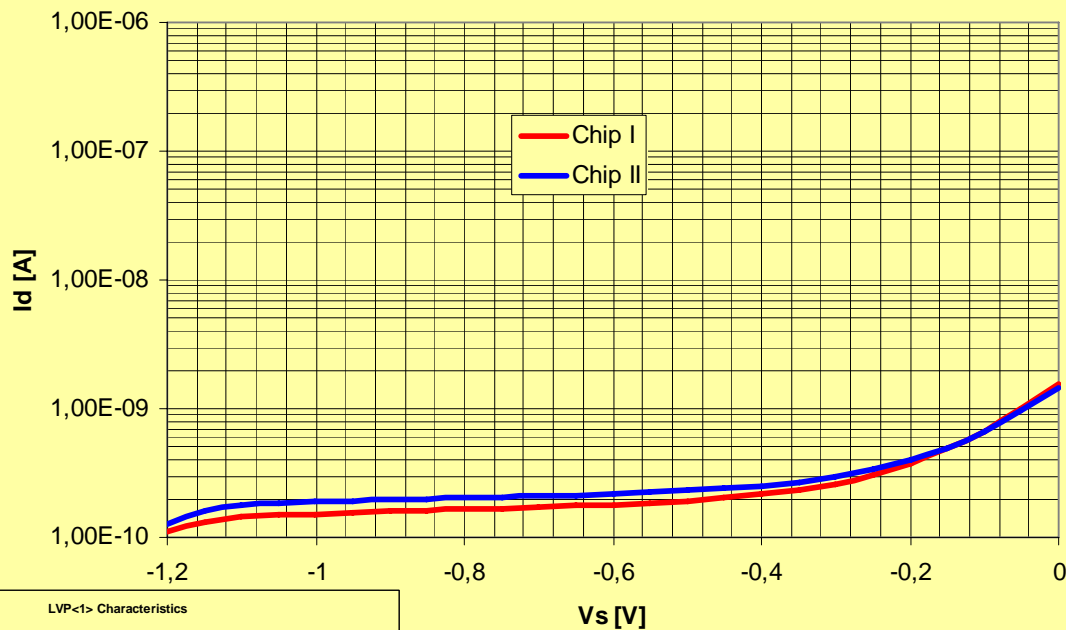
$W=3.04\mu\text{m}$   
 $L=0.24\mu\text{m}$   
 $N=200$



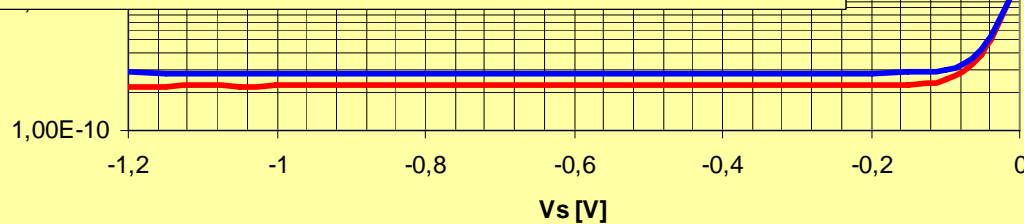
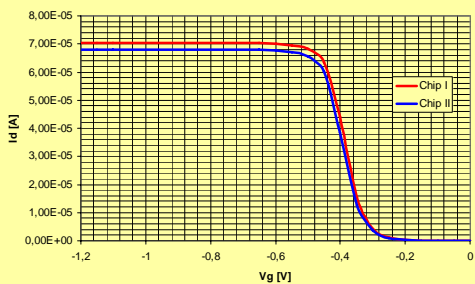
# LPPMOS<1>

$W=3.04\mu\text{m}$   
 $L=0.12\mu\text{m}$   
 $N=100$

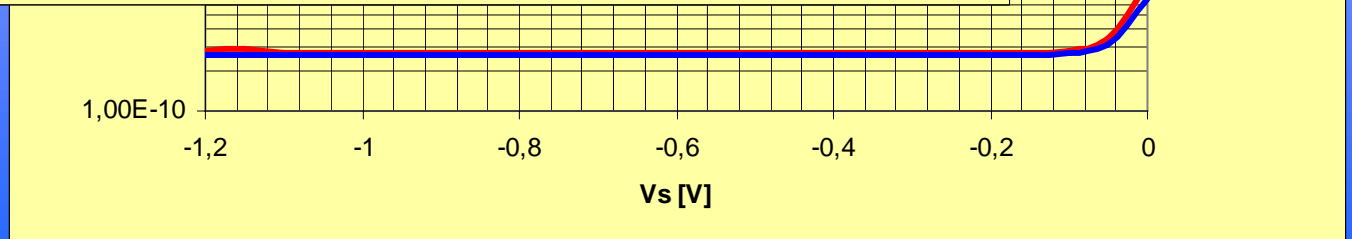
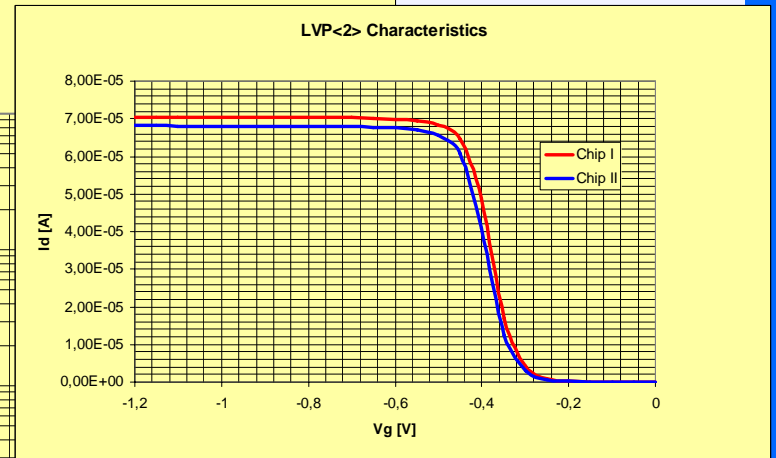
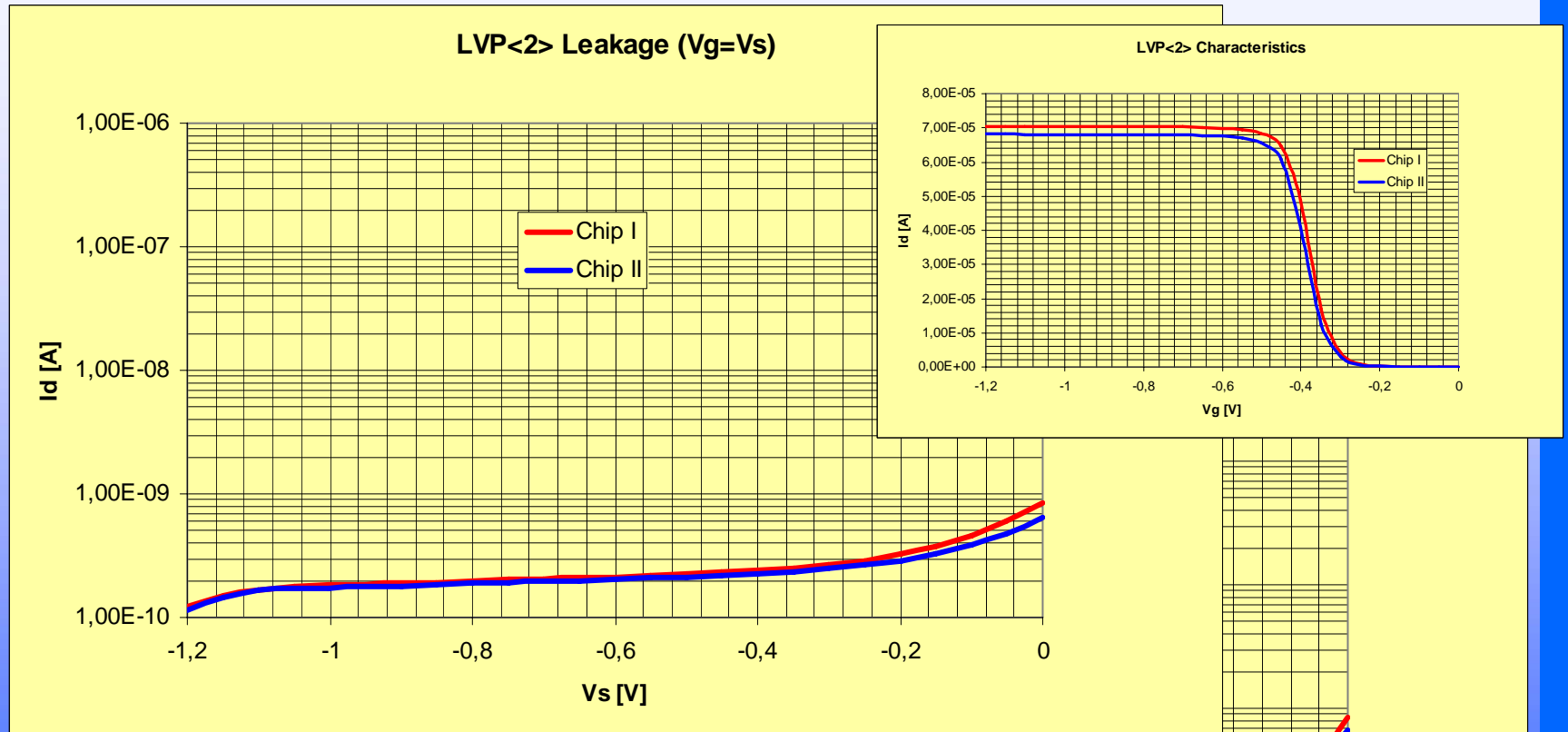
LVP<1> Leakage ( $V_g=V_s$ )



LVP<1> Characteristics



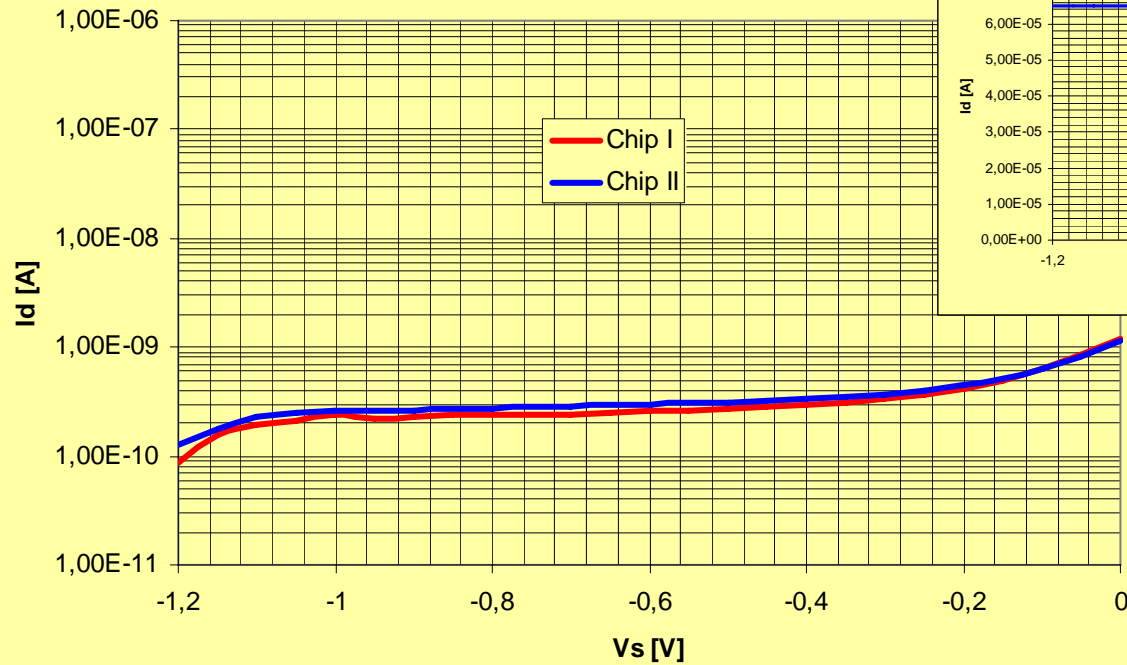
# LPPMOS<2>



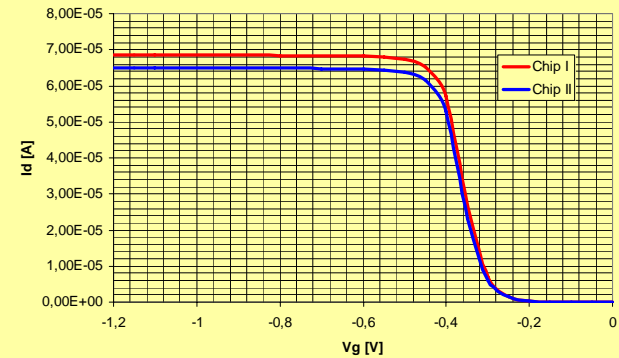
$W=3.04\mu\text{m}$   
 $L=0.24\mu\text{m}$   
 $N=100$

# LPPMOS<3>

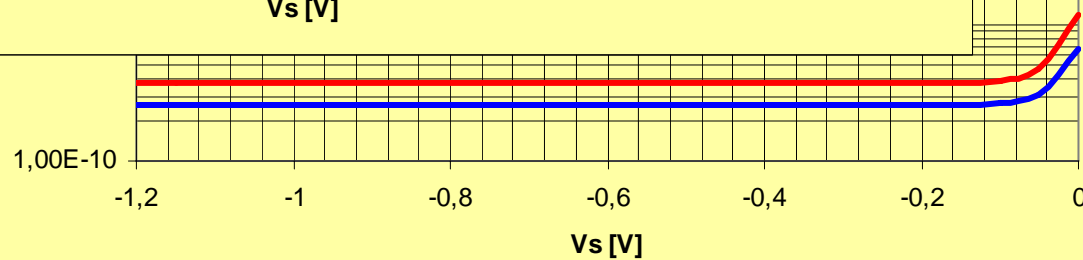
LVP<3> Leakage ( $V_g=V_s$ )



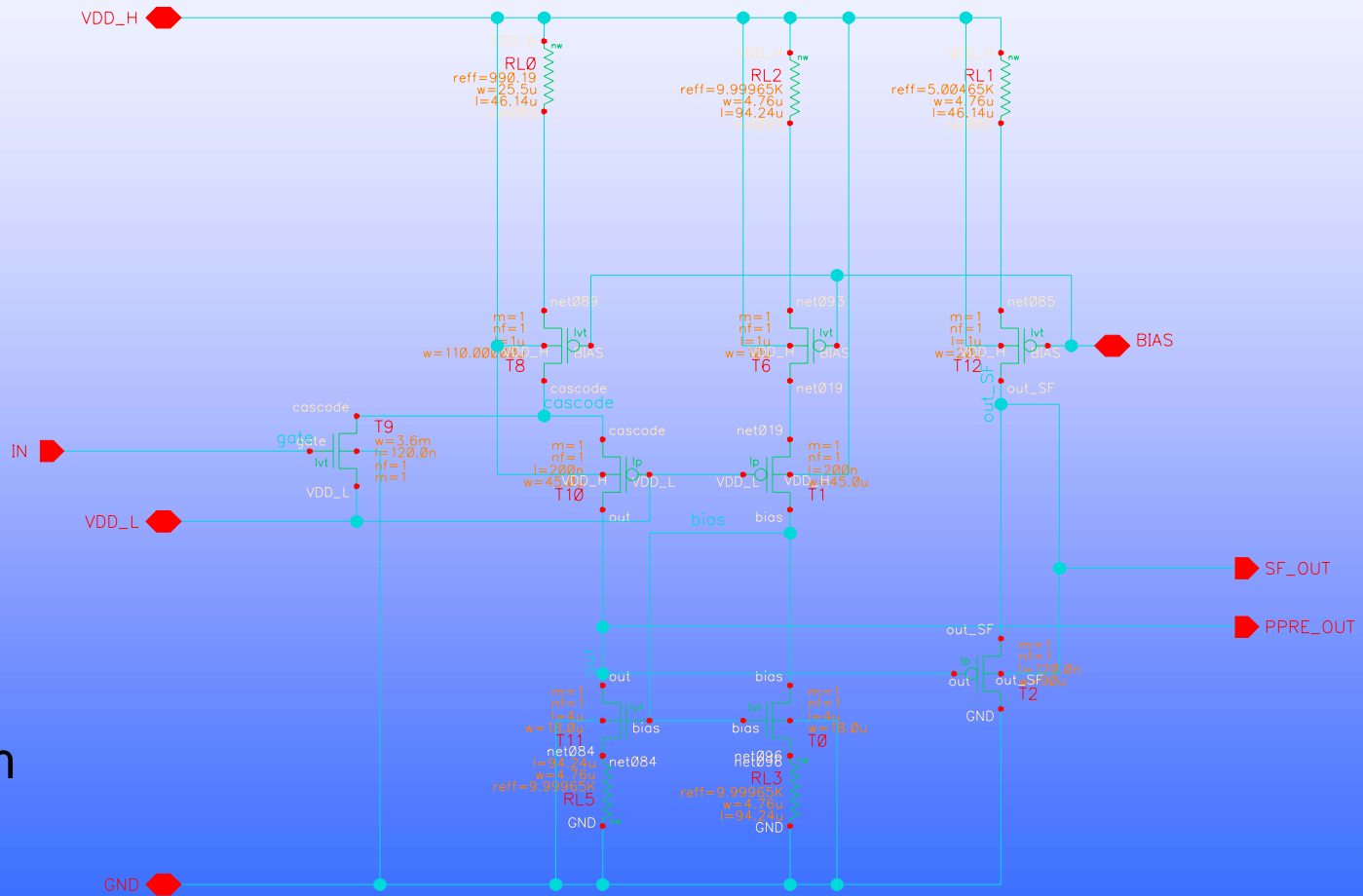
LVP<3> Characteristics



**W=3.04 $\mu$ m**  
**L= 0.24 $\mu$ m**  
**N= 200**



# Folded Cascode Preamp



**W= 3600um**  
**L= 0.12um**  
**NMOS**  
**I= 50uA**



# Folded Cascode Preamp + Shaper?

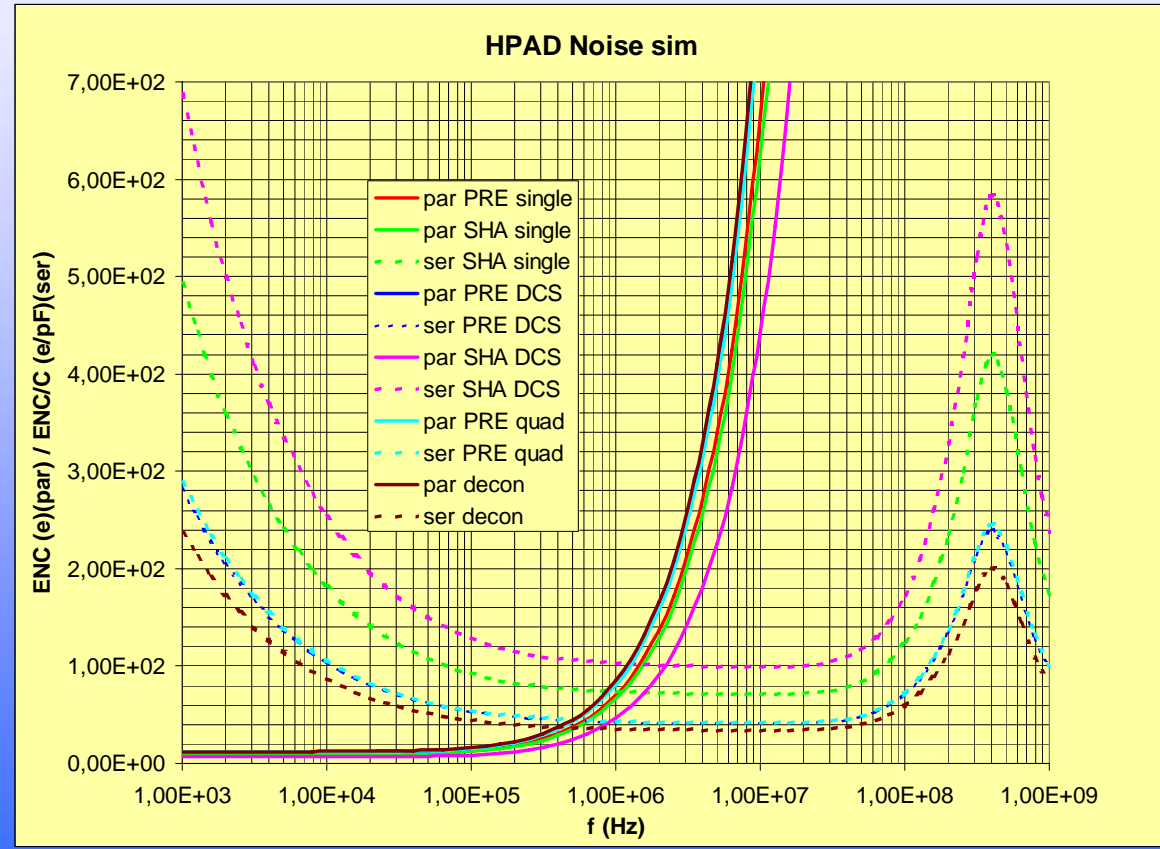
Pulse processing		Noise ( $ENC^2$ )	
Sampling	Filter	parallel	series
single	none	$\frac{i_{np}^2}{2} \cdot 0.535 T_{meas}$	$\infty$
single	$CR - RC$	$\frac{i_{np}^2}{2} \cdot 0.475 T_{meas}$	$\frac{e_{ns}^2}{2} C_p \cdot 7.18/T_{meas}$
double	none	$\frac{i_{np}^2}{2} \cdot 0.750 T_{meas}$	$\frac{e_{ns}^2}{2} C_p \cdot 2.54/T_{meas}$
double	$CR - RC$	$\frac{i_{np}^2}{2} \cdot 0.238 T_{meas}$	$\frac{e_{ns}^2}{2} C_p \cdot 15.2/T_{meas}$
quad	none	$\frac{i_{np}^2}{2} \cdot 0.731 T_{meas}$	$\frac{e_{ns}^2}{2} C_p \cdot 2.68/T_{meas}$
deconvolution		$\frac{i_{np}^2}{2} \cdot 0.786 T_{meas}$	$\frac{e_{ns}^2}{2} C_p \cdot 1.80/T_{meas}$

W. Fallot-Burghardt: *A CMOS Mixed-Signal Readout Chip for the Microstrip Detectors of HERA-B*

DCS+CR-RC:

- Shaper will suppress transients from gain switching
  - Shaped pulse after the peak (2nd sample) is not evaluated
- > Reset of shaper?

# Folded Cascode Preamp + Shaper?



# Conclusions

## Measurements on "HPAD 0.1"

- Surprises, but
- No conclusions so far, since
  - Results are not (yet) consistent
  - No irradiation data

## Preamplifier

- Simulations look promising, but
  - No Shaper design yet
  - Ideas for implementation of gain switching exist
  - No simulation of preamp, shaper & gainswitching yet



Work in Progress!